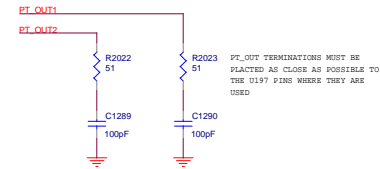
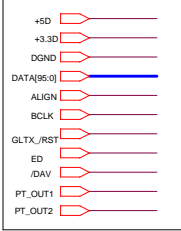
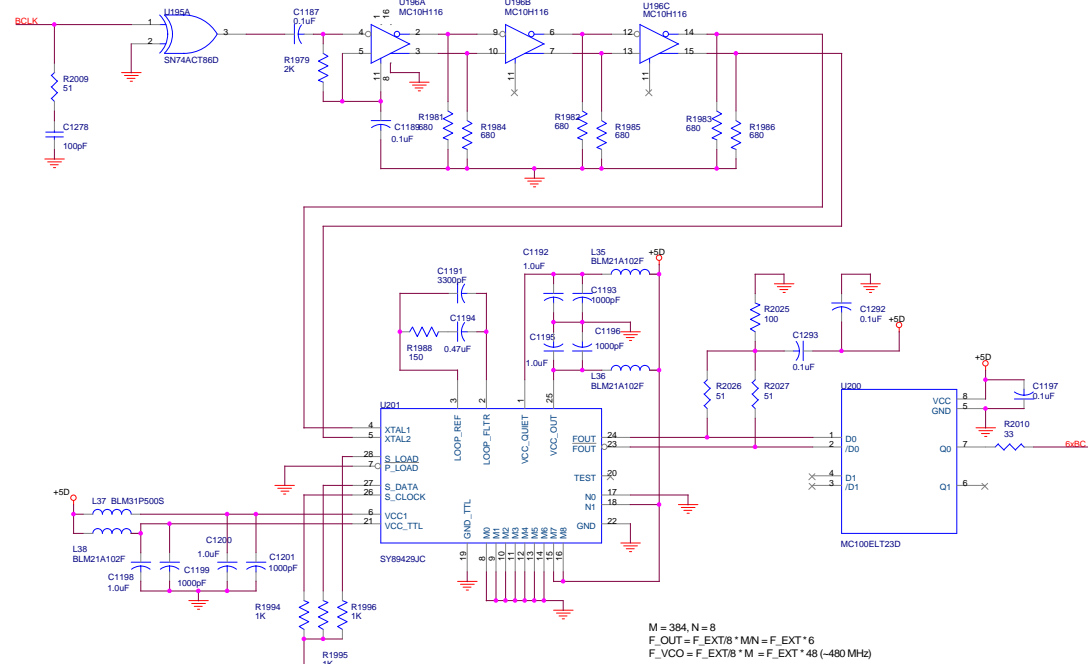
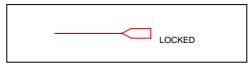


# INPUTS

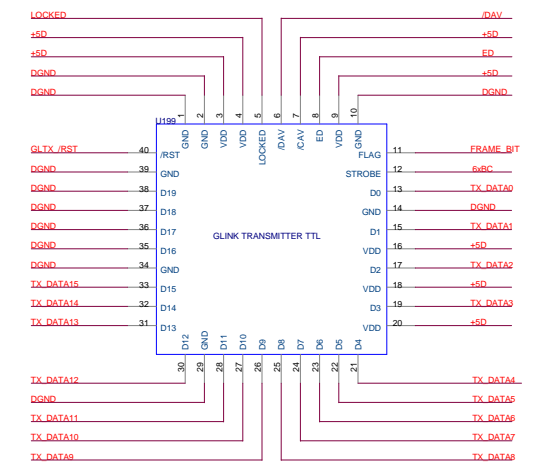
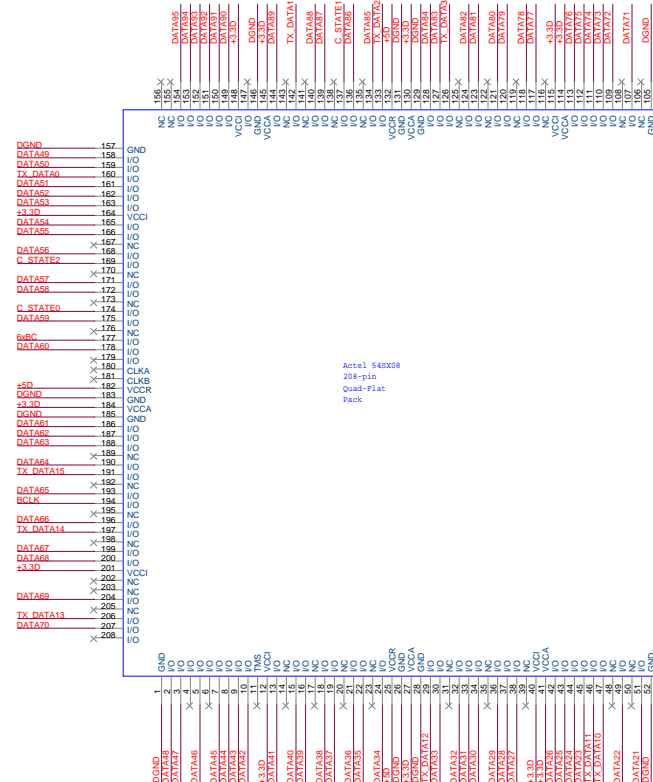


PT\_OUT TERMINATIONS MUST BE PLACED AS CLOSE AS POSSIBLE TO THE U197 PINS WHERE THEY ARE USED.

# OUTPUTS



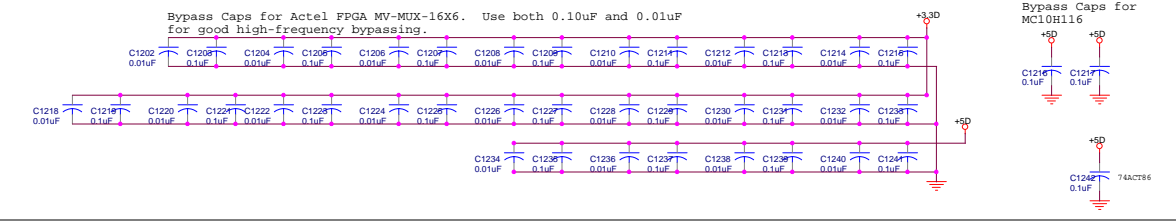
M = 384, N = 8  
 F\_OUT = F\_EXT8 \* MN = F\_EXT \* 6  
 F\_VCO = F\_EXT8 \* M = F\_EXT \* 48 (~480 MHz)



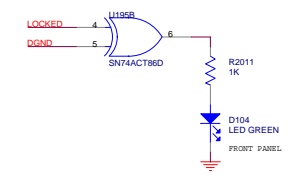
**GLINK MODULE CONNECTOR**  
 SEA ADVANCED INTERCONNECTIONS PART NUMBER K8010-21070 SOCKETS ARE USED TO MOUNT THE GLINK MODULE

## POWER SUPPLY BYPASS CIRCUITS

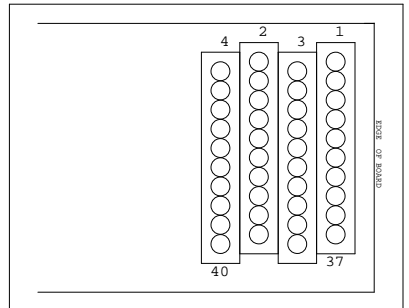
Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.



Notes:  
 1) Place parts as close as possible to keep traces short in general. High speed traces require special attention.  
 2) High speed traces must be kept short. Short means less than 1.7 inches. They must also be routed to avoid vias. Traces should stay on a single layer whenever possible.

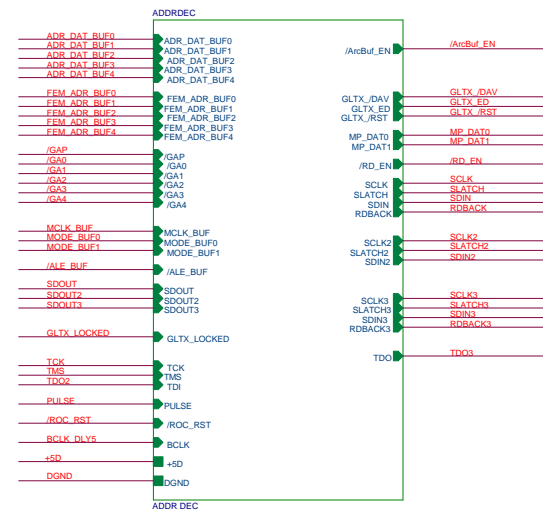
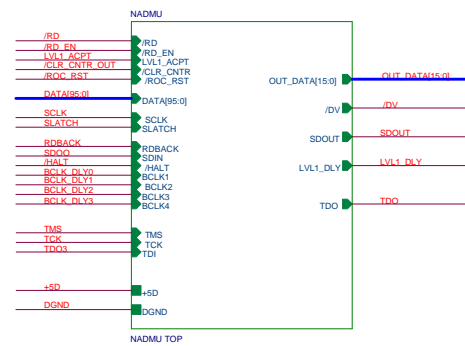
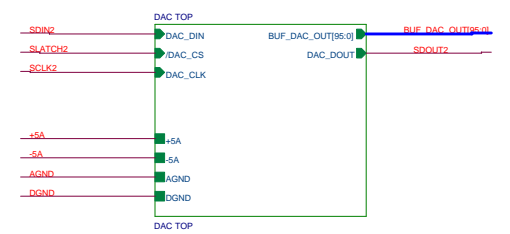
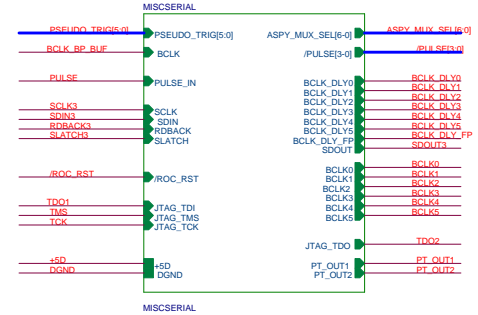
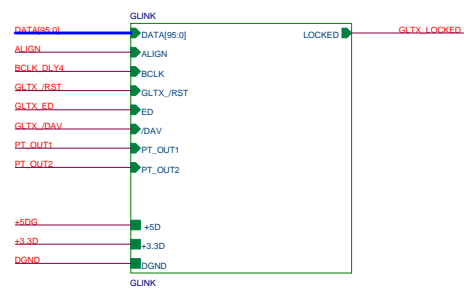
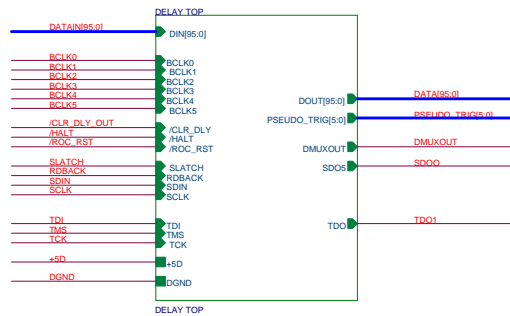
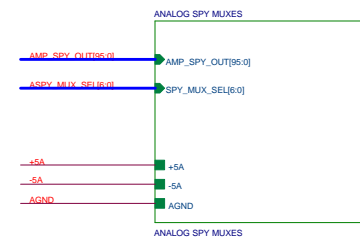
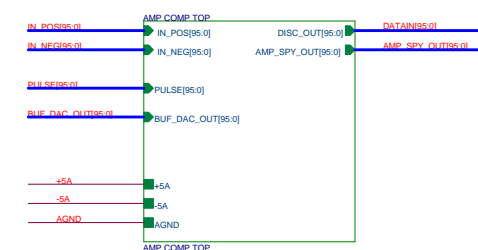
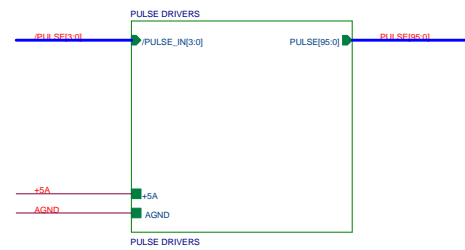
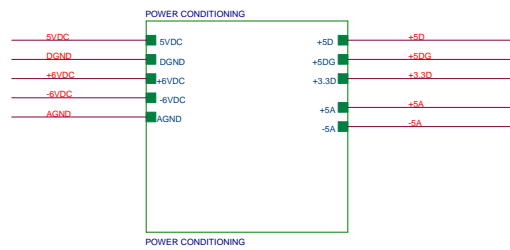


## TOP VIEW OF GLINK TTL CONNECTOR



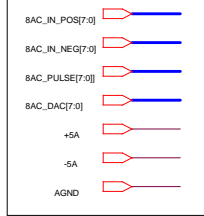
**CHANGES FROM REV0**  
 1. ADDED PT\_OUT1 and PT\_OUT2 SIGNALS TO GLINK CHIP  
 2. REPLACED 1013-50 CHIP WITH 1013-25  
 3. ADDED SOURCE TERMINATION RESISTOR TO 6XBC SIGNAL  
 4. MODIFIED BCLK TERMINATION  
 5. MODIFIED PLL OUTPUT TERMINATION AND POWER FILTERING ACCORDING TO MICREL AN06

**Phenix MulD ROC**  
 Oak Ridge National Lab  
 Instrumentation and Controls Division  
 File: GLINK  
 Date: Tuesday, October 03, 2000 8:58am 1 of 34

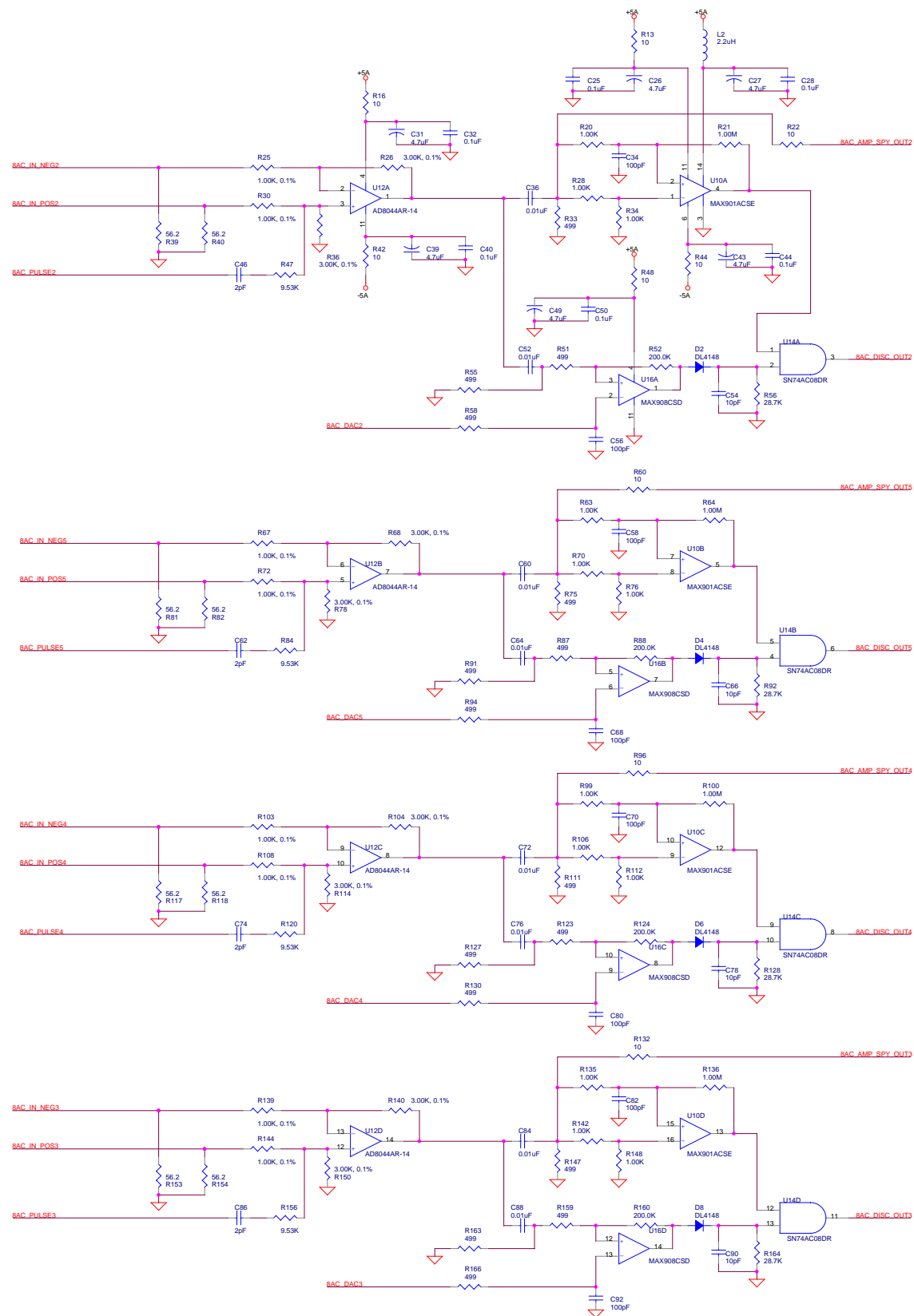
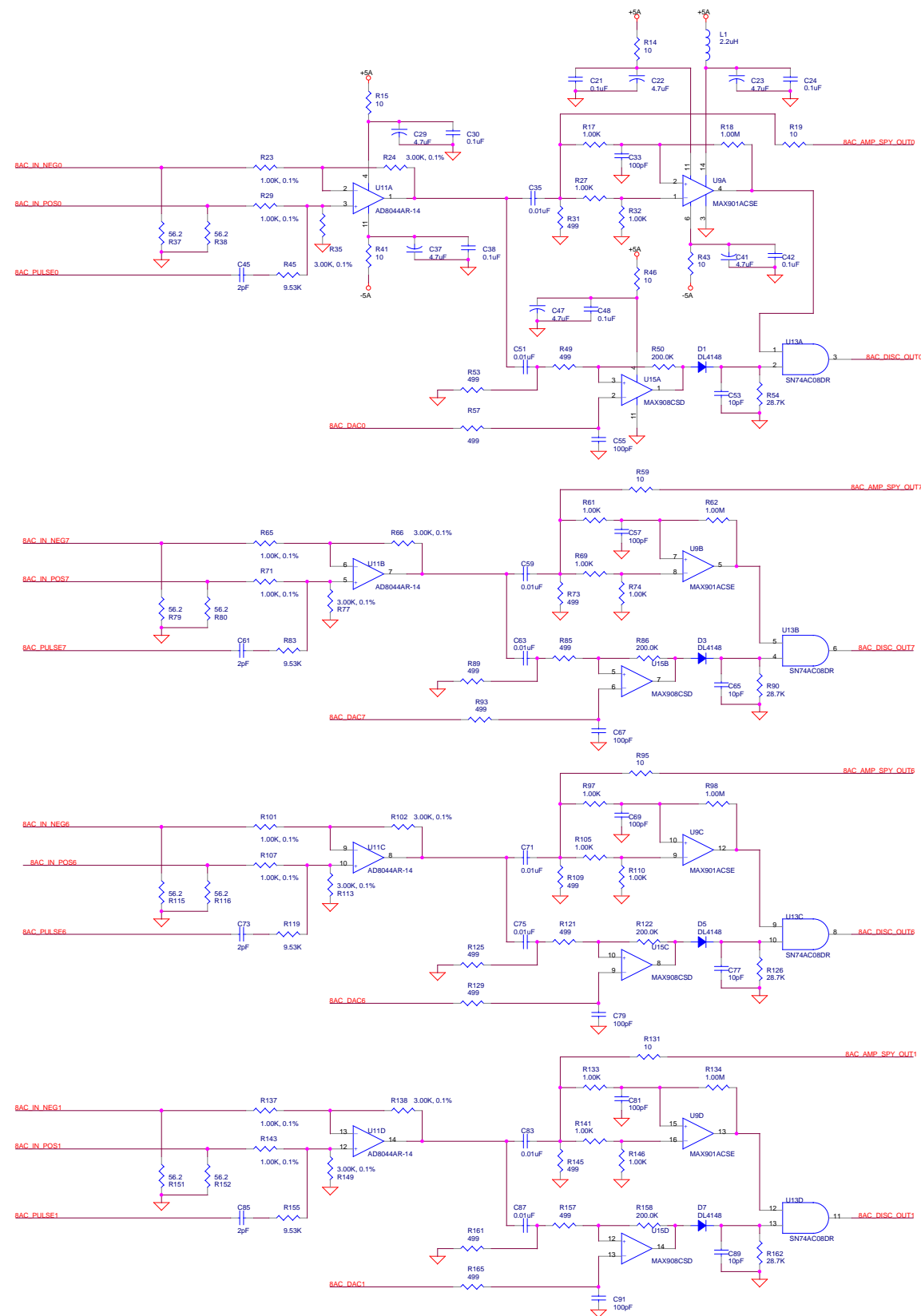


**CHANGES FROM REV0**  
 1. ADDED FIVE EVENT FIFO TO JTAG LOOP  
 2. ADDED PULSE, BCLK\_DLY, AND PULSE LINES TO ADDRESS DECODER  
 3. ADDED DGND TO DAC INPUT  
 4. CHANGED DGND TO AGND ON PULSE DRIVERS  
 5. ELIMINATED /RSET SIGNALS

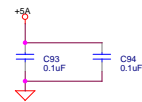
### INPUTS



### OUTPUTS



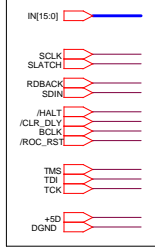
BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS



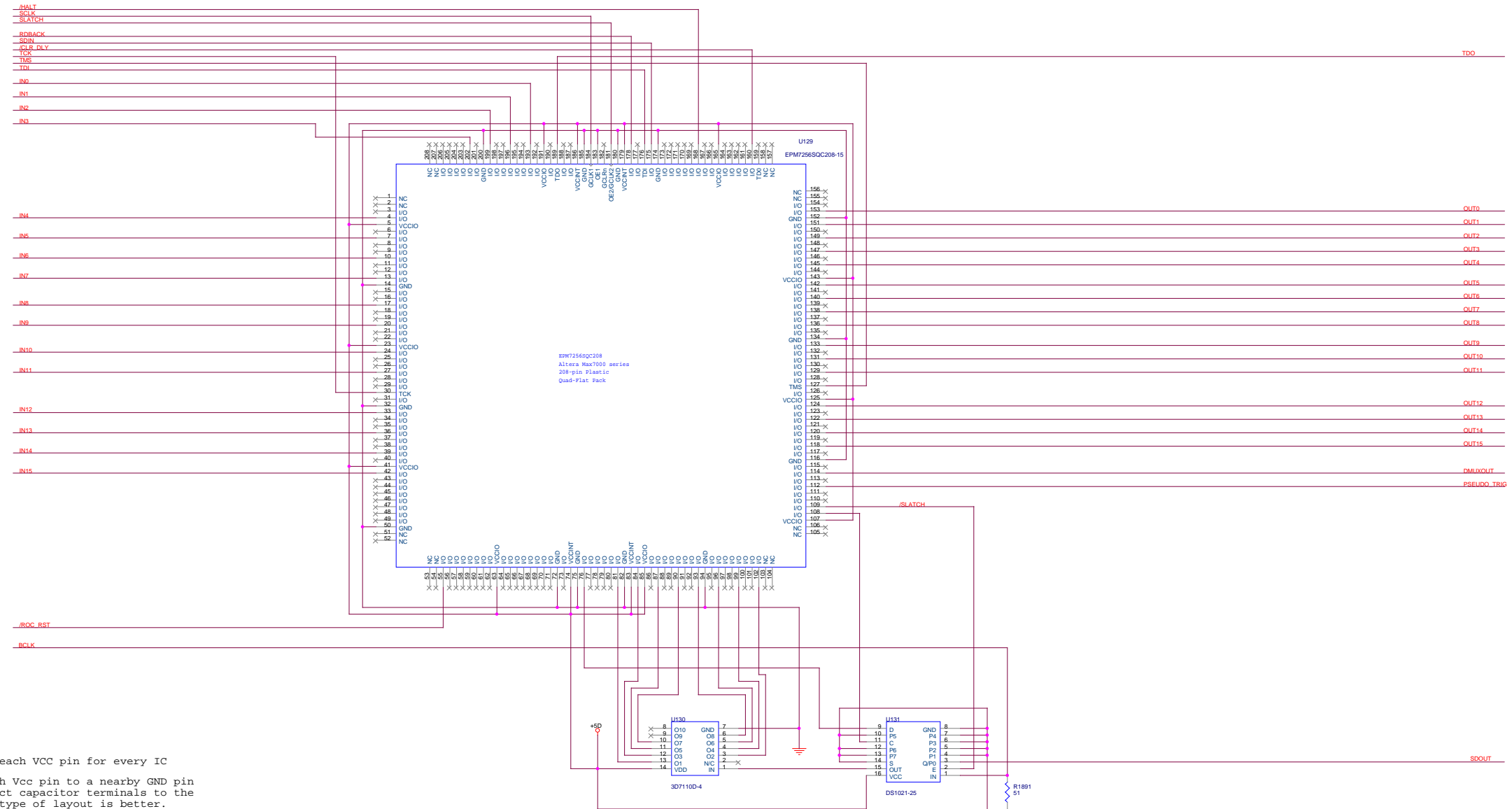
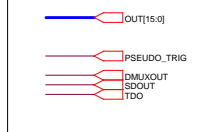
- CHANGES FROM REV0**
1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF
  2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

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Oak Ridge National Lab  
Instrumentation and Controls Division

### INPUTS

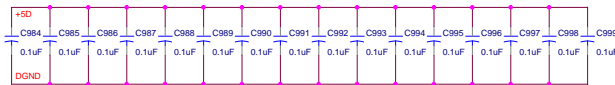


### OUTPUTS



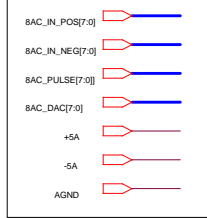
Place bypass caps next to each VCC pin for every IC

Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.

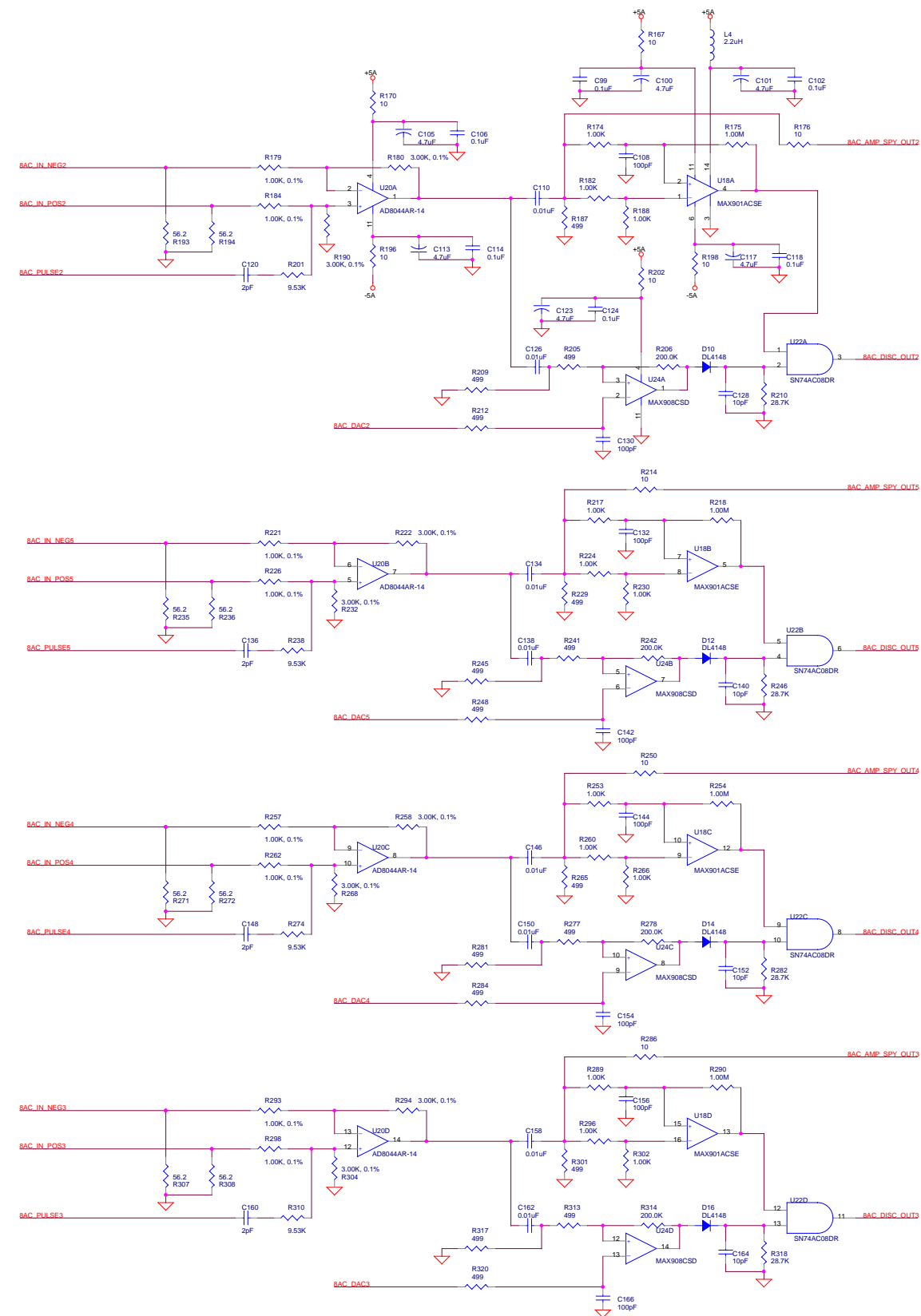
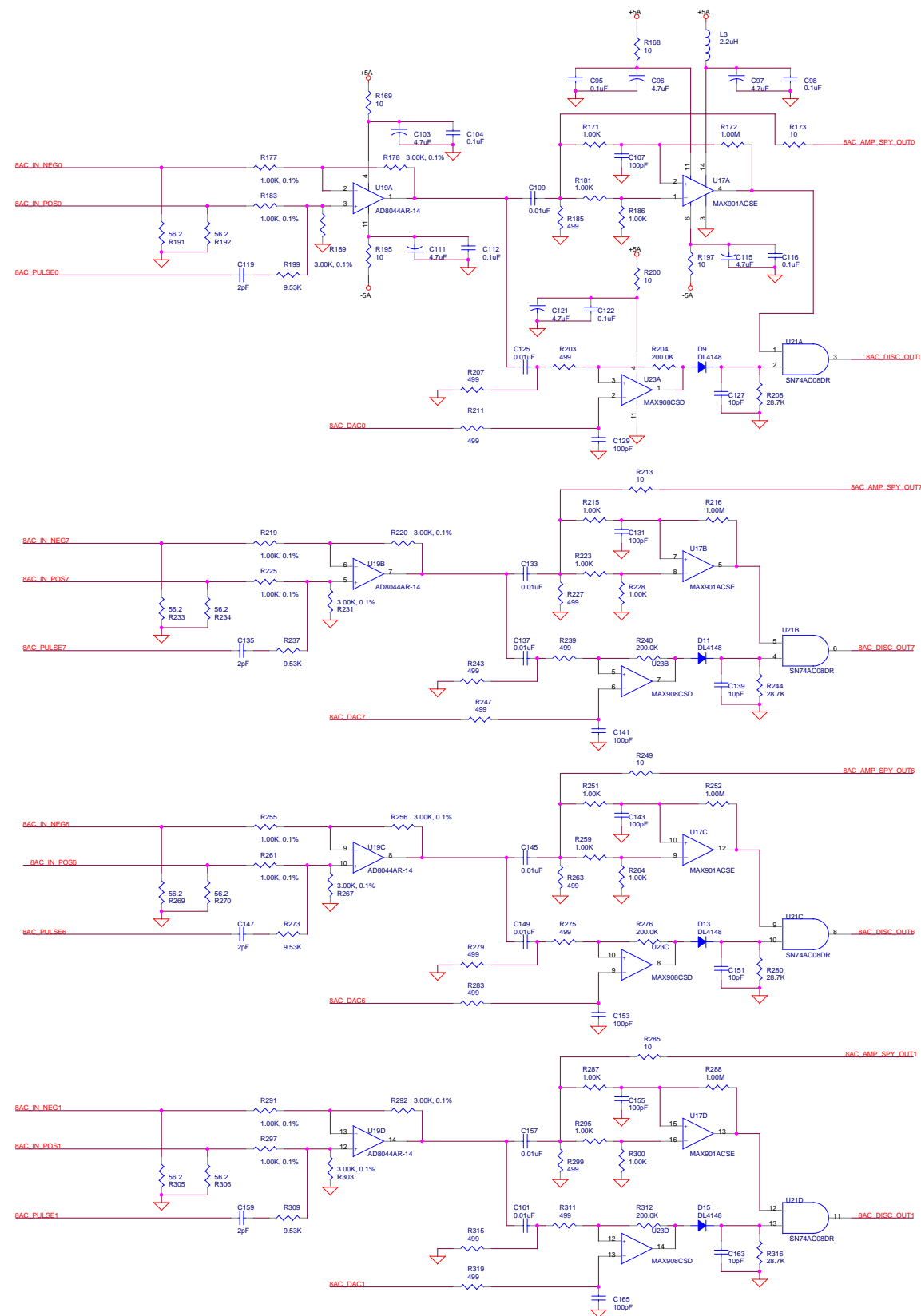
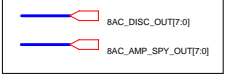


- CHANGES FROM REV0**
1. CHANGED BCLK TERMINATION
  2. 1021 CHIP SCLK CONNECTED TO CONDITIONED SIGNAL TO ALLOW SERIAL READBACK
  3. REMOVED CLR\_SRL SIGNAL
  4. REMOVED PULL-UP RESISTORS FROM DELAY CHIP

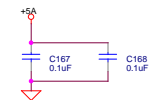
### INPUTS



### OUTPUTS

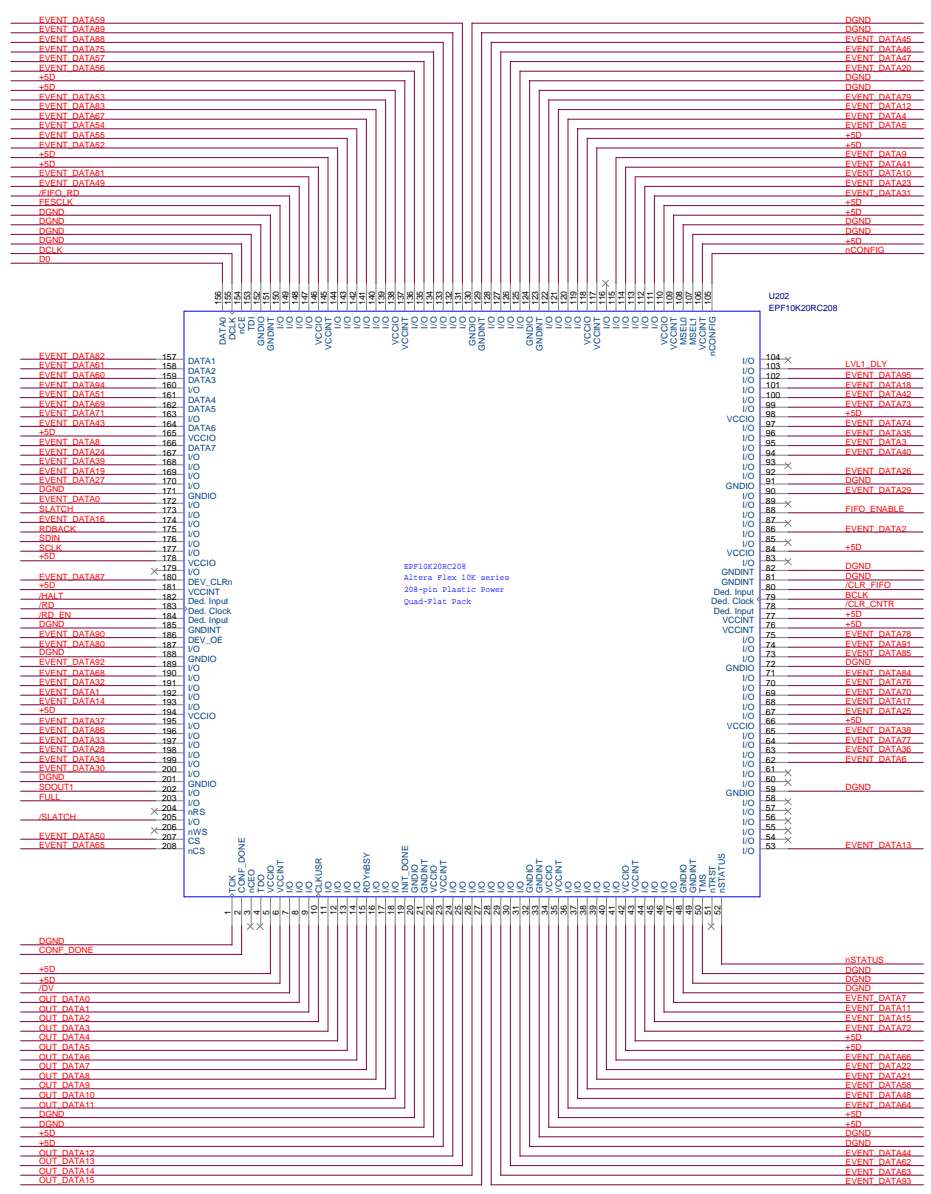
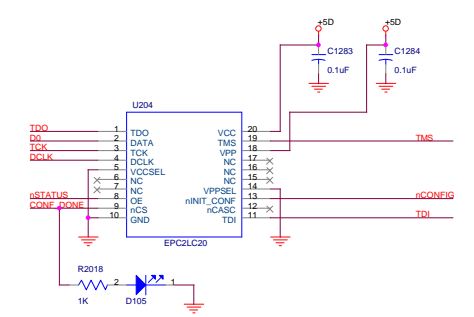
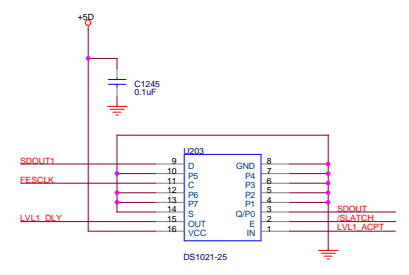
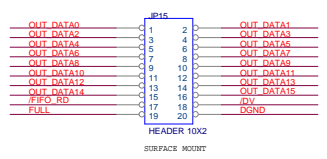
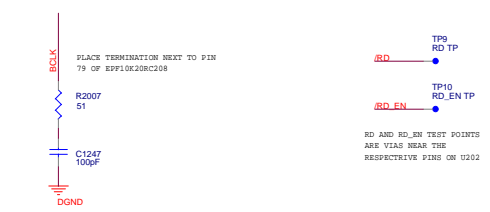
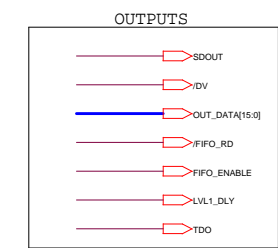
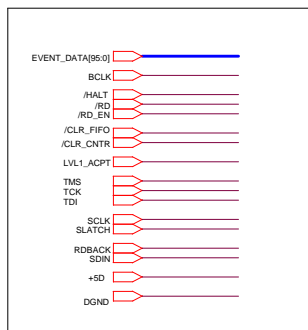


BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS

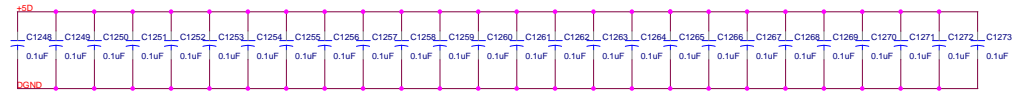


- CHANGES FROM REV0**
1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF
  2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

# INPUTS

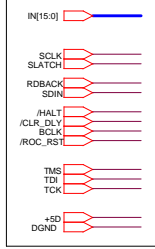


Place bypass caps next to pins 5, 6, 22, 23, 34, 35, 42, 43, 66, 76, 77, 84, 98, 106, 109, 110, 117, 118, 137, 138, 145, 146, 165, 178, 181, and 194 of EPP10K20RC208  
Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.

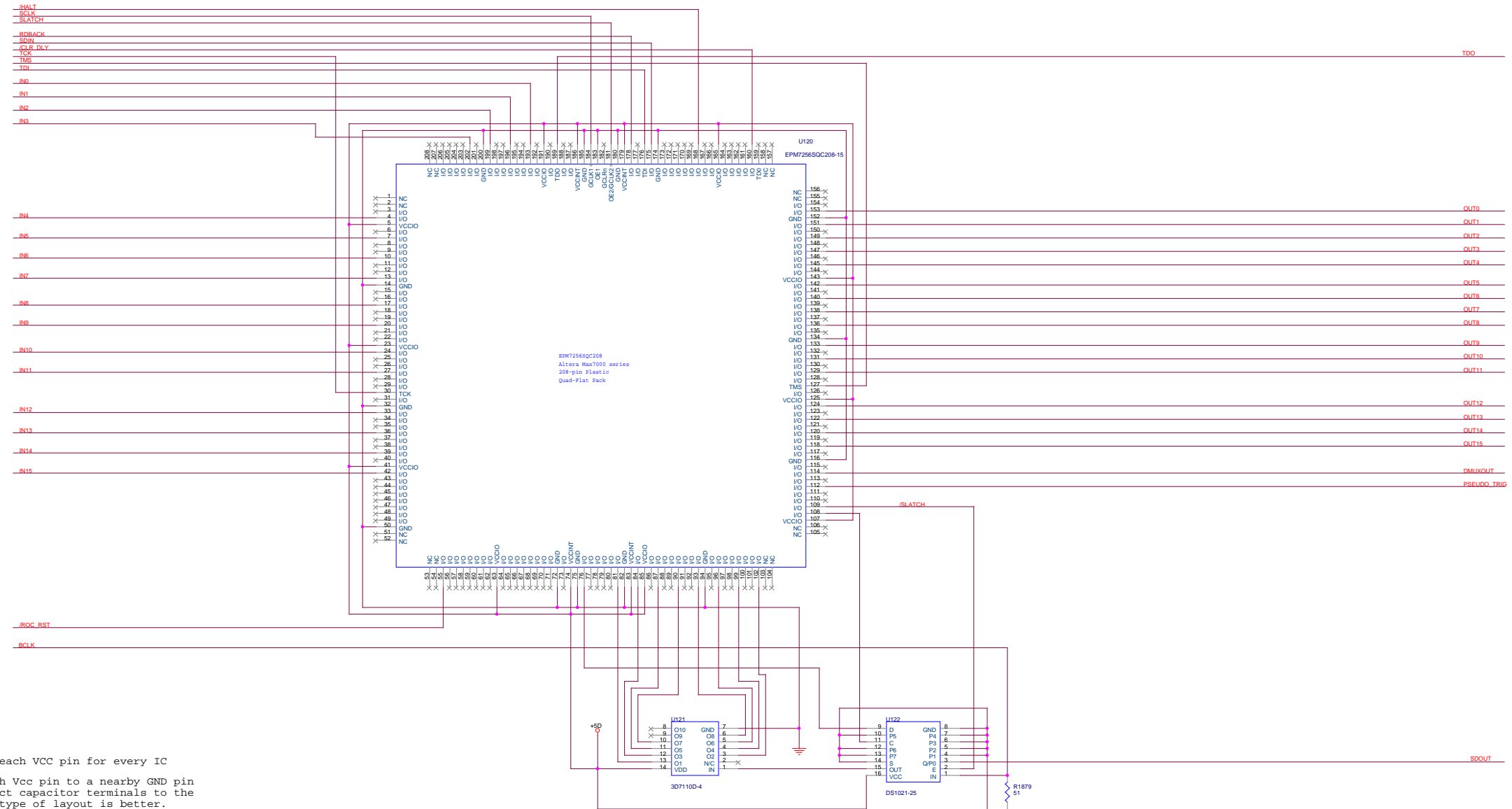
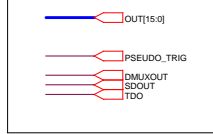


- ### CHANGES FROM REV0
1. ADDED /HALT SIGNAL TO FIVE EVENT FIFO
  2. ADDED JTAG I/O
  3. CHANGED EEPROM TO GO ON COMMON JTAG LOOP
  4. CHANGED TEST HEADER TO SURFACE MOUNT PART
  5. CHANGED BCLK TERMINATION VALUES

### INPUTS

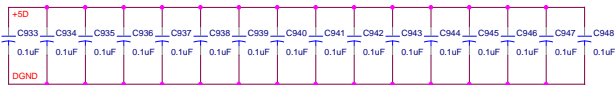


### OUTPUTS



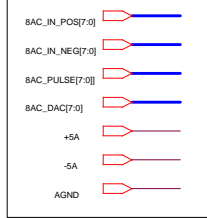
Place bypass caps next to each VCC pin for every IC

Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.

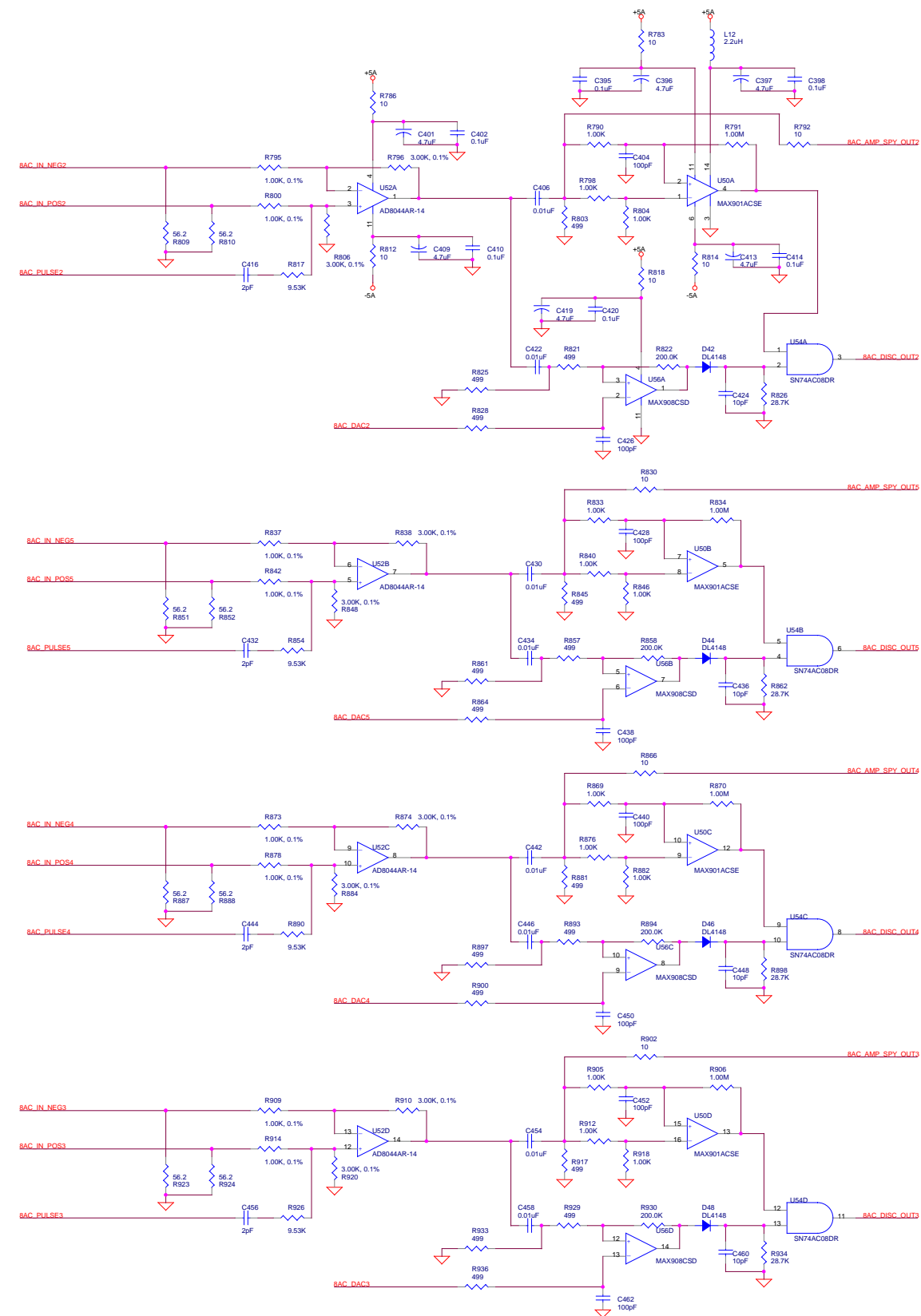
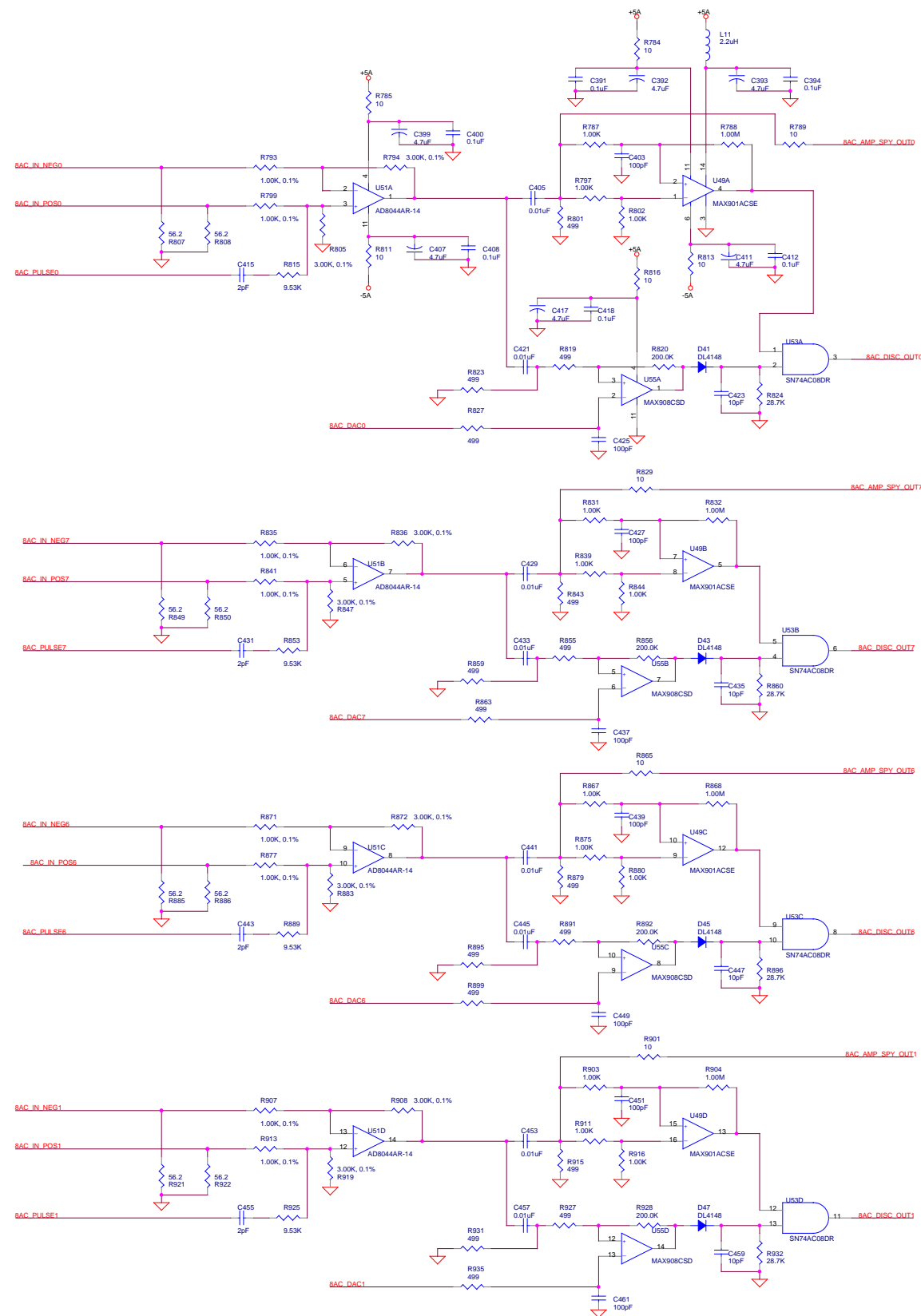
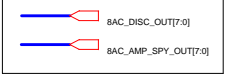


- CHANGES FROM REV0**
1. CHANGED BCLK TERMINATION
  2. 1021 CHIP SCLK CONNECTED TO CONDITIONED SIGNAL TO ALLOW SERIAL READBACK
  3. REMOVED CLR\_SRL SIGNAL
  4. REMOVED PULL-UP RESISTORS FROM DELAY CHIP

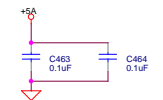
### INPUTS



### OUTPUTS



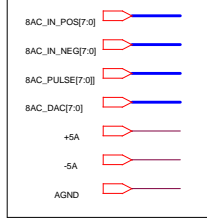
BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS



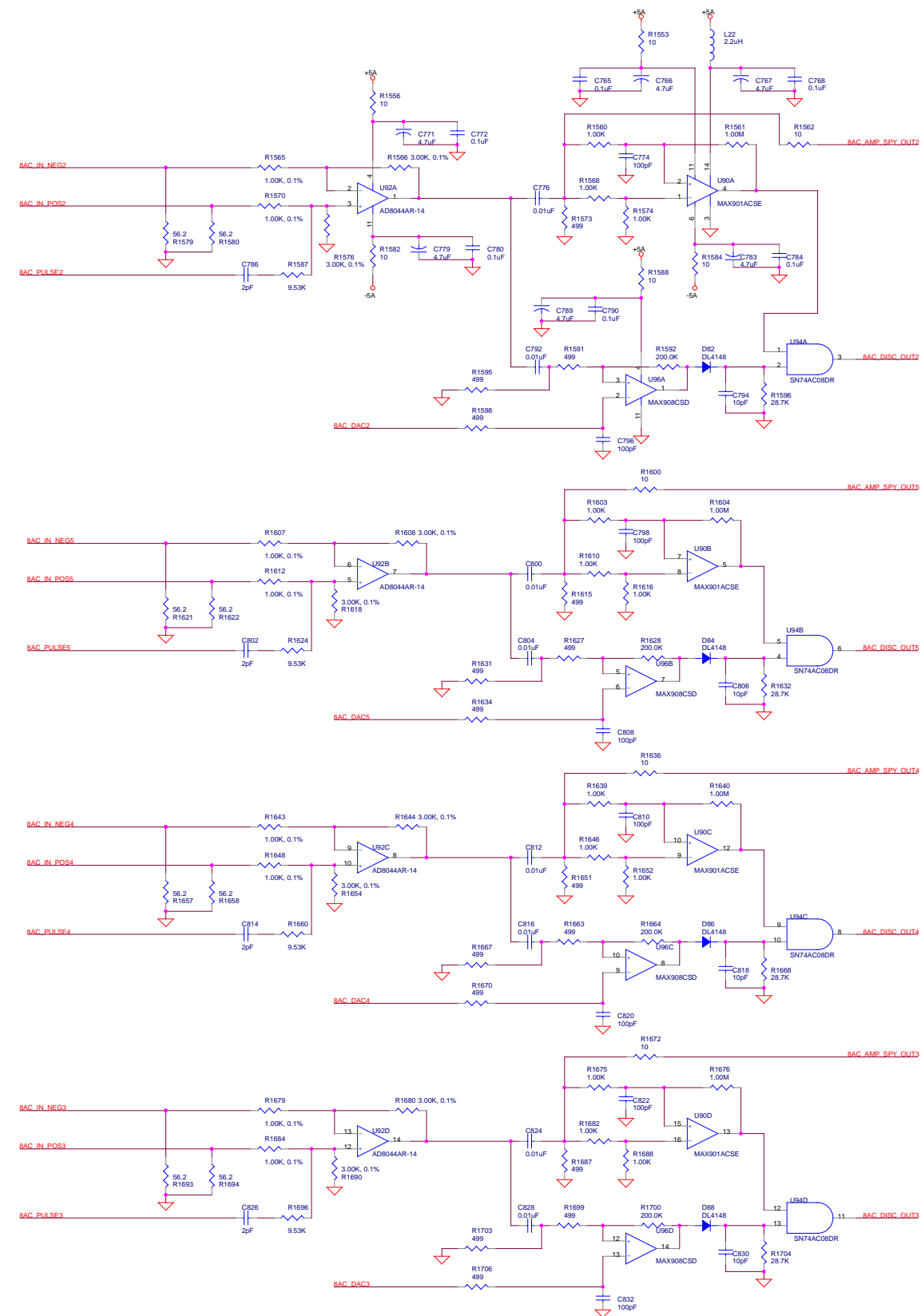
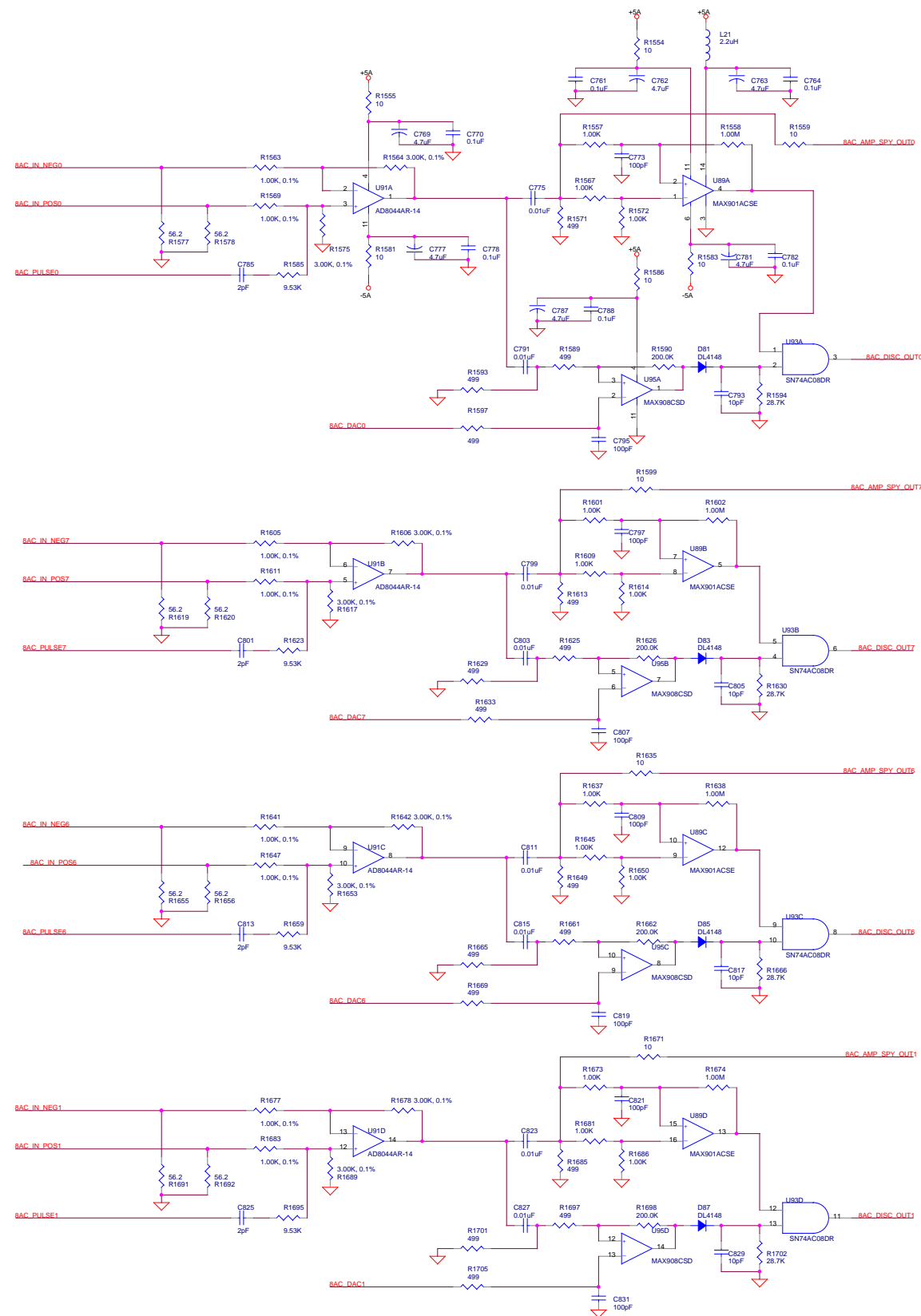
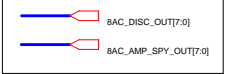
**CHANGES FROM REV0**  
 1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF  
 2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K



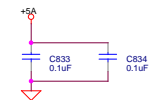
### INPUTS



### OUTPUTS

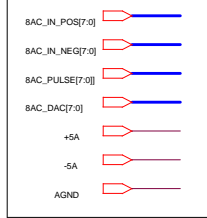


BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS

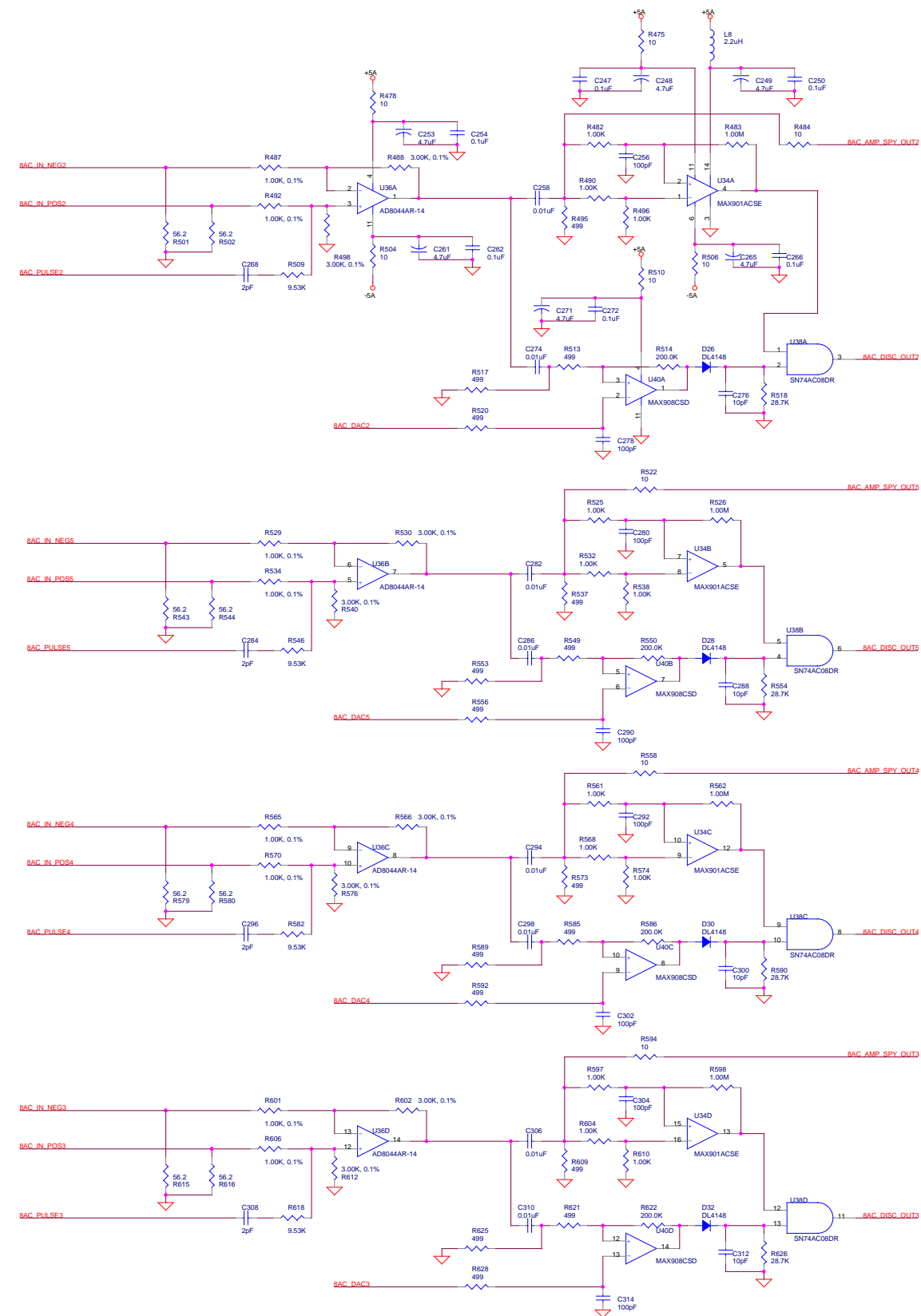
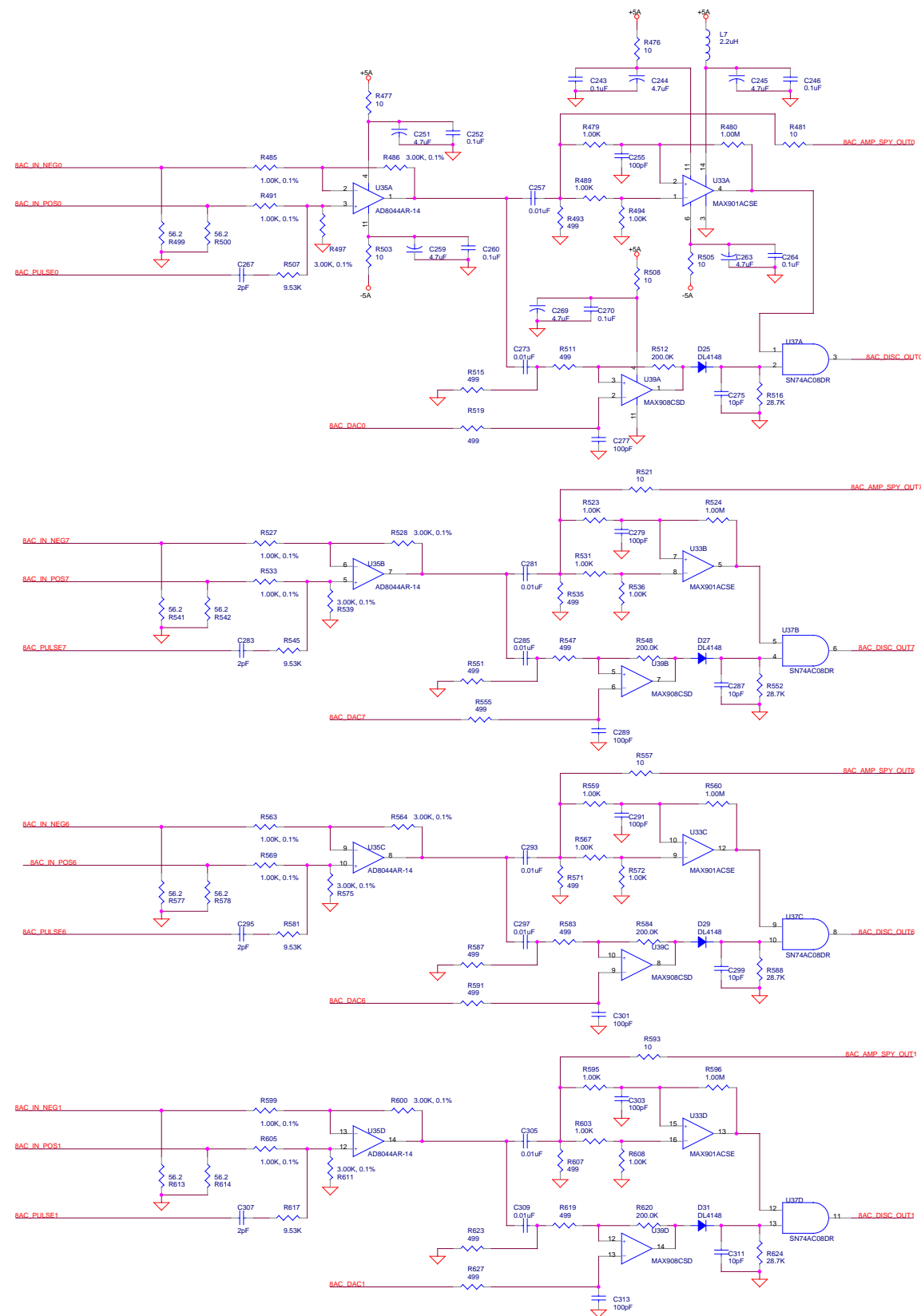


- CHANGES FROM REV0**
1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF
  2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

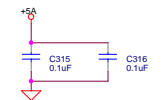
### INPUTS



### OUTPUTS

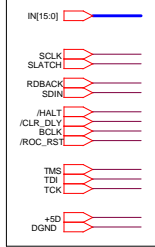


BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS

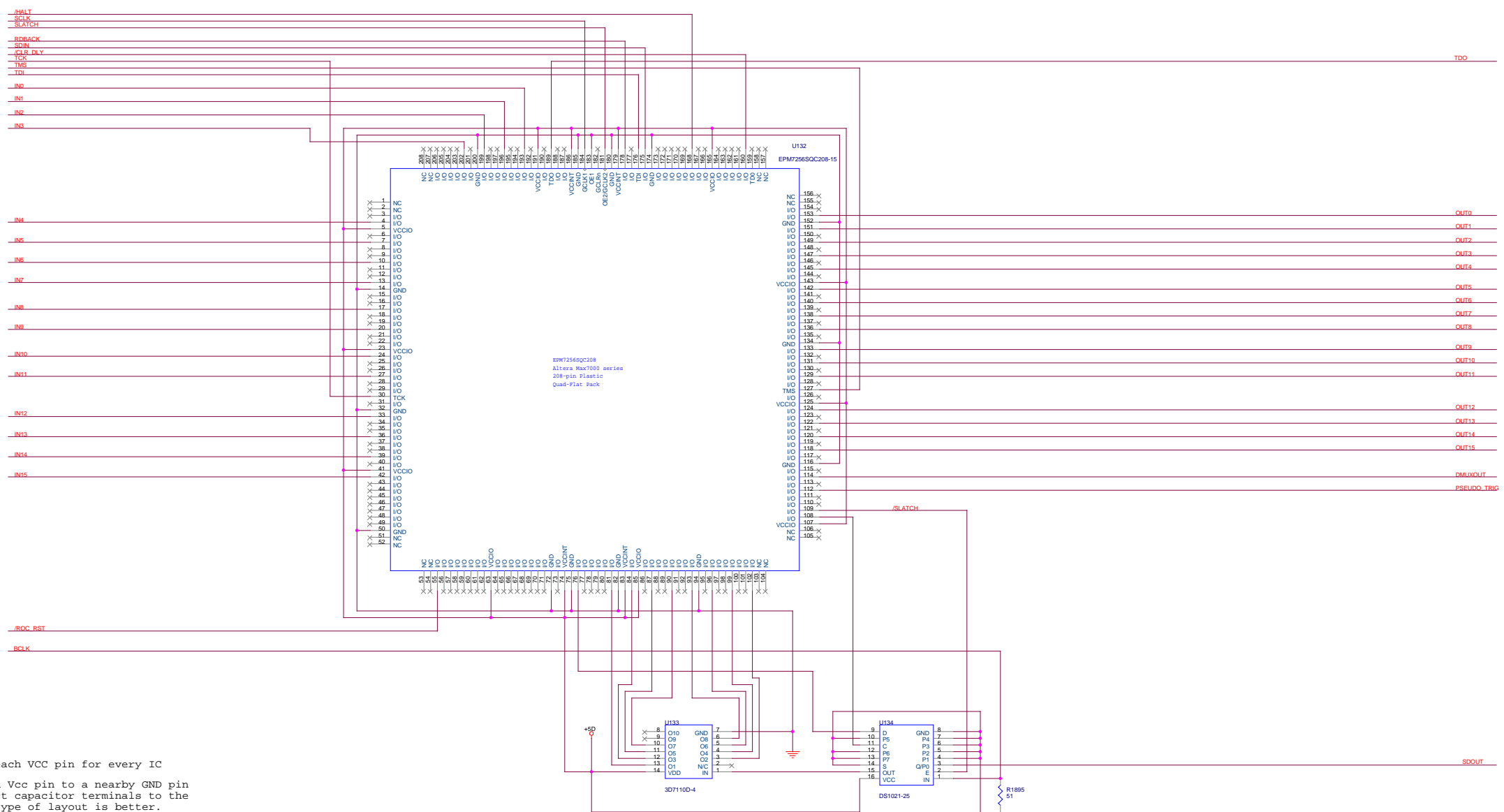
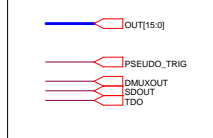


**CHANGES FROM REV0**  
 1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF  
 2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

### INPUTS

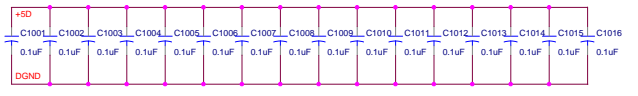


### OUTPUTS



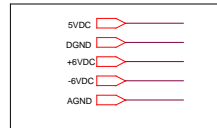
Place bypass caps next to each VCC pin for every IC

Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.



- CHANGES FROM REV0**
1. CHANGED BCLK TERMINATION
  2. 1021 CHIP SCLK CONNECTED TO CONDITIONED SIGNAL TO ALLOW SERIAL READBACK
  3. REMOVED CLR\_SRL SIGNAL
  4. REMOVED PULL-UP RESISTORS FROM DELAY CHIP

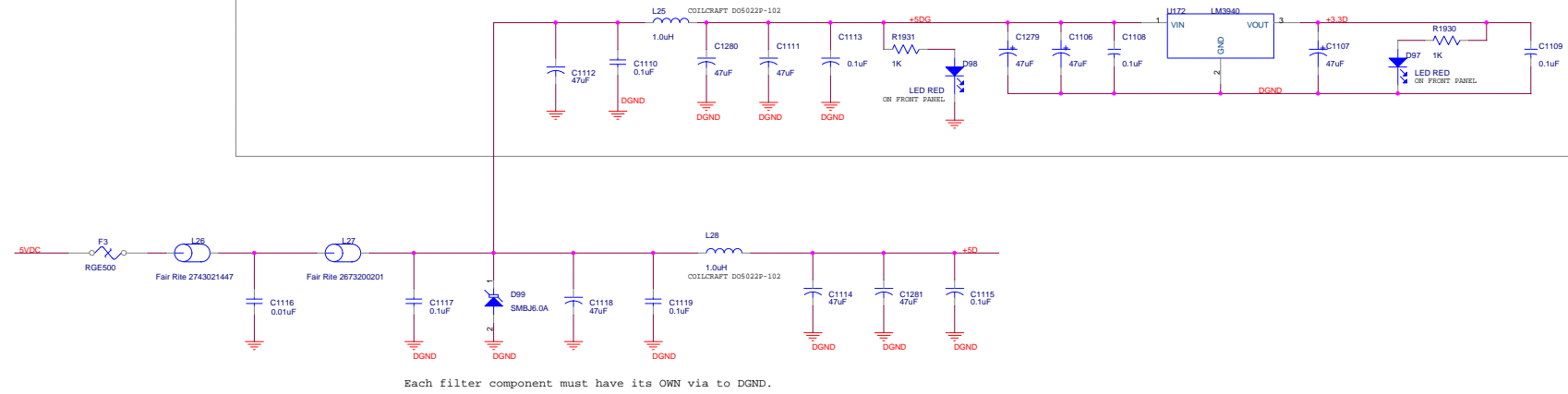
### INPUTS



### DIGITAL POWER CONDITIONING

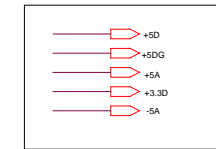
NEED TO HANDLE 5 AMPS.

COMPONENTS IN THIS BOX MUST BE LOCATED NEAR THE GLINK POWER PLANE AND THE INPUT TO THIS SECTION MUST BE A LARGE TRACE

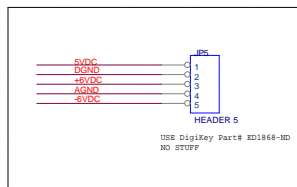


Each filter component must have its OWN via to DGND.

### OUTPUTS



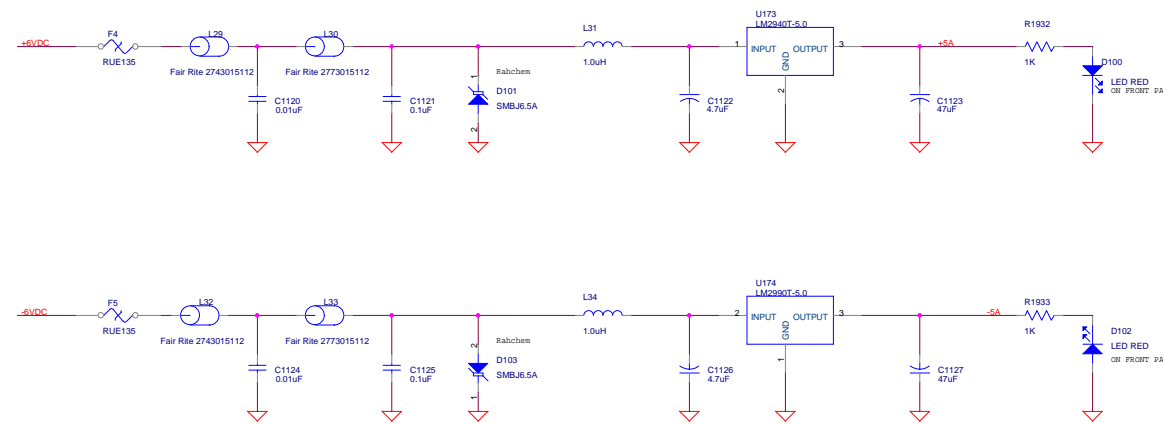
### ALTERNATE POWER INPUT CONNECTOR



ALL LEDS ARE SIZE T! AND MOUNTED ON FRONTPANEL

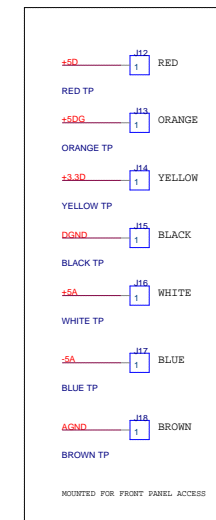
### ANALOG POWER CONDITIONING

NEED TO HANDLE 1 AMPS.



Each filter component must have its OWN via to DGND.

### TEST POINTS

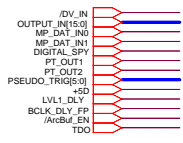


- CHANGES FROM REV0**
1. ADDED FRONT PANEL TEST POINTS
  2. CHANGED 100uF CAPACITORS TO SURFACE MOUNT
  3. CHANGED FILTER COILS TO PART RATED FOR HIGHER CURRENT
  4. CHANGED TAN. CAPS TO USE AVAIL. PARTS
  5. CHANGED LED RESISTORS TO 1K FOR UNIFORMITY

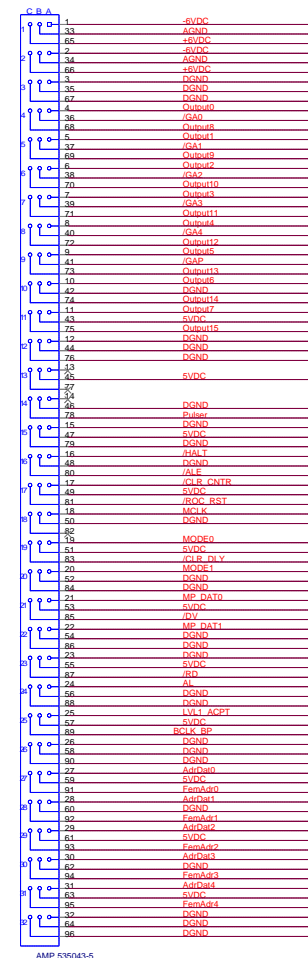
Phenix MuID ROC  
Oak Ridge National Lab  
Instrumentation and Controls Division

File	POWER CONDITIONING
Rev	D
Document Number	5.3.13.002-0313-110
Date	Tuesday, October 03, 2000
Sheet	12 of 34

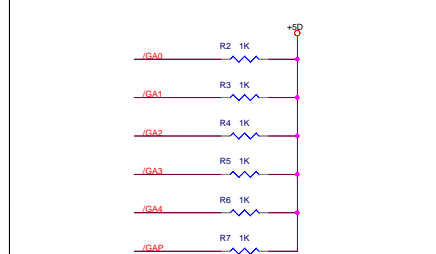
### INPUTS



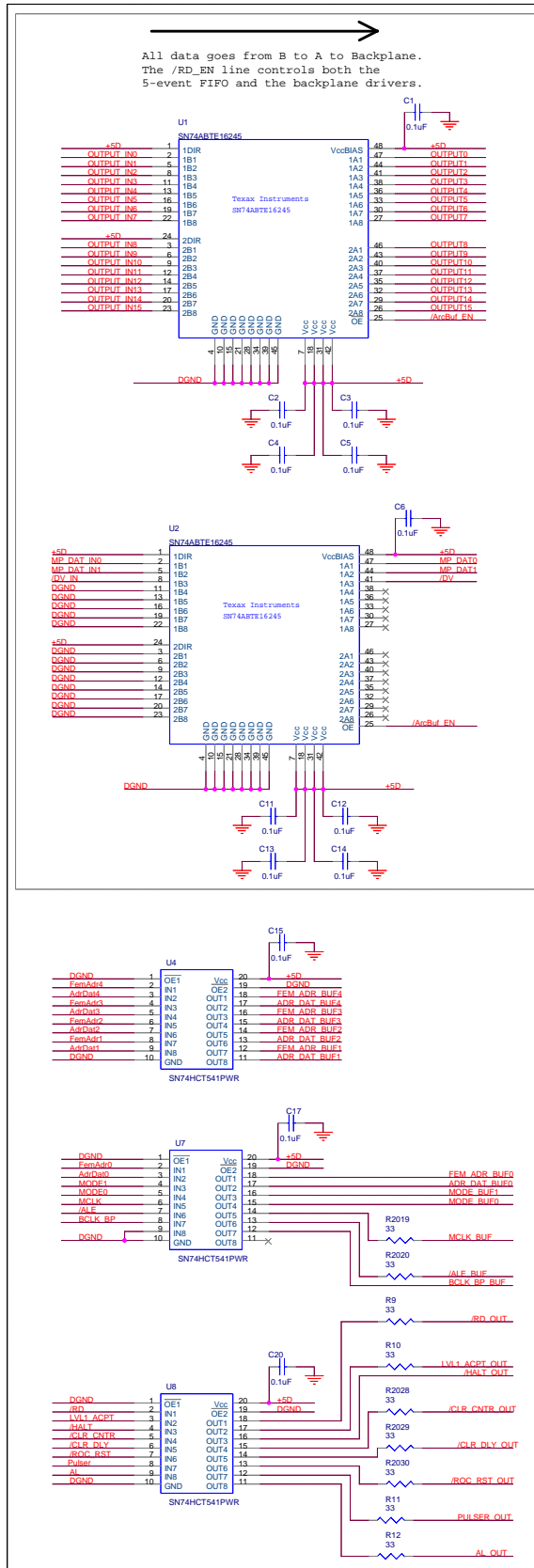
### DIGITAL BACKPLANE CONNECTOR



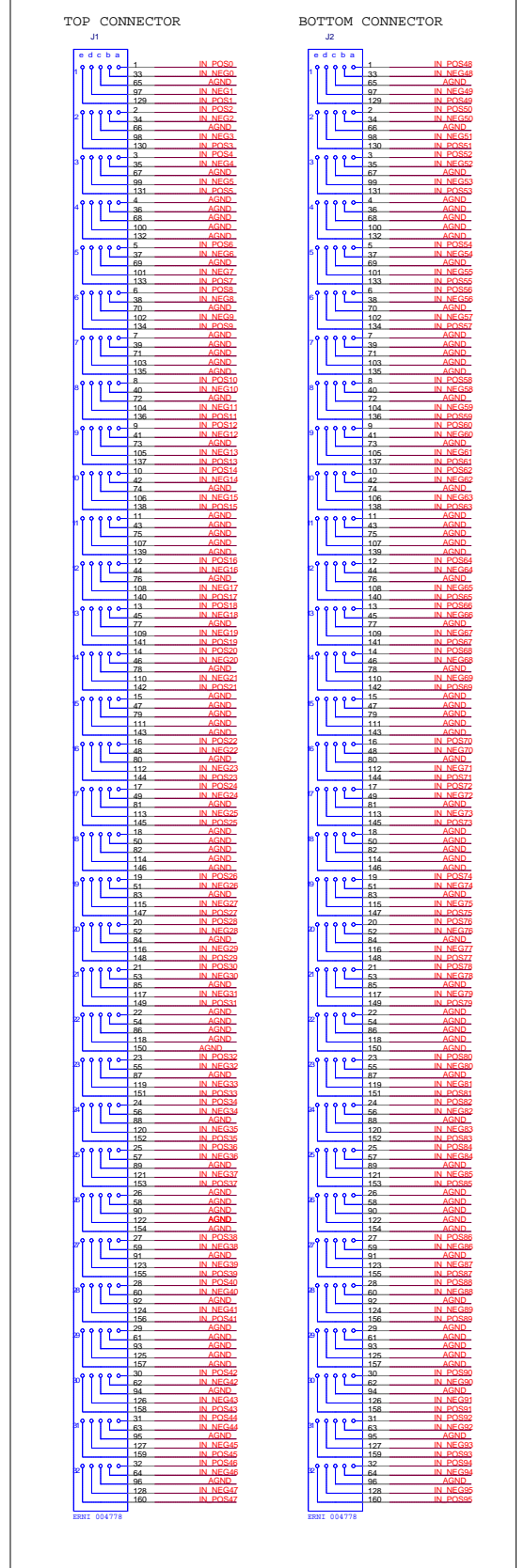
### GLOBAL ADDRESS PULL-UPS



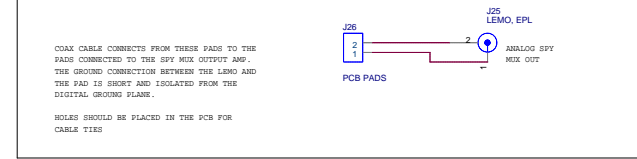
### VME BUS DRIVERS AND RECEIVERS



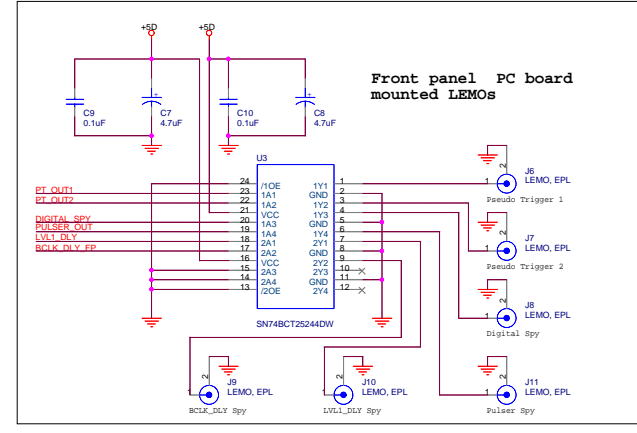
### ANALOG INPUT CONNECTORS



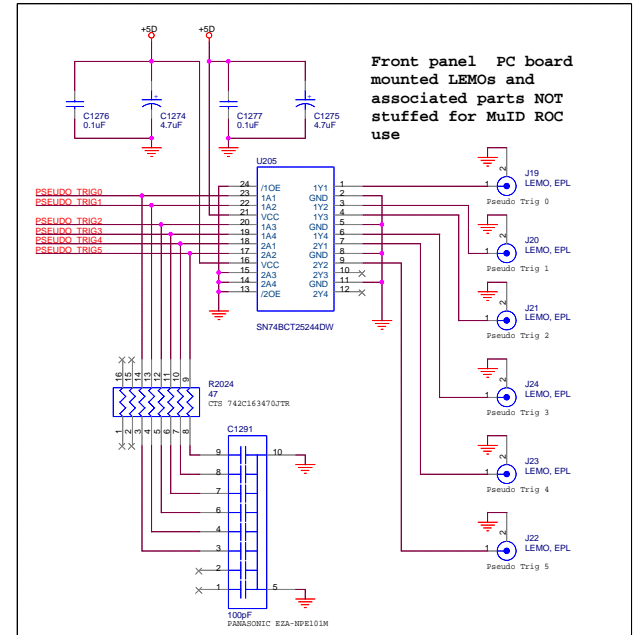
### FRONT PANEL ANALOG SPY OUTPUT



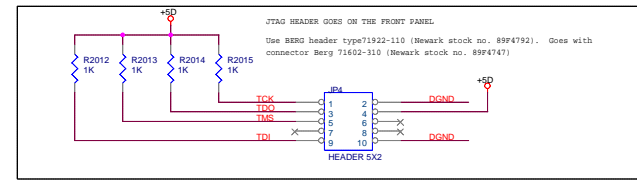
### FRONT PANEL 50 OHM TTL OUTPUTS



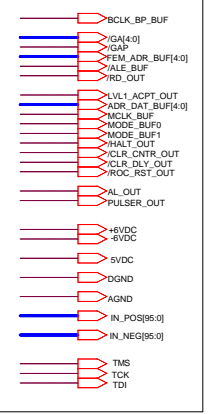
### PSEUDO TRIGGER OUTPUTS



### JTAG CONNECTOR

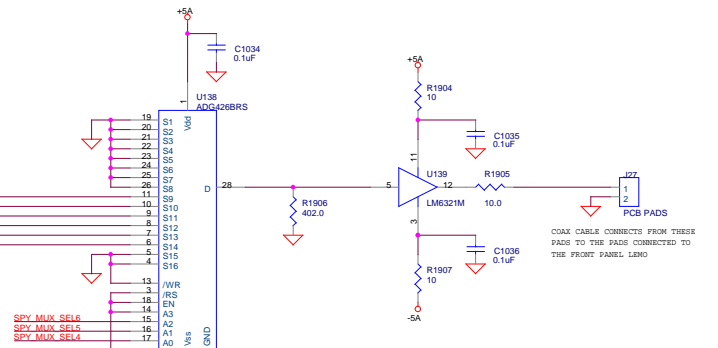
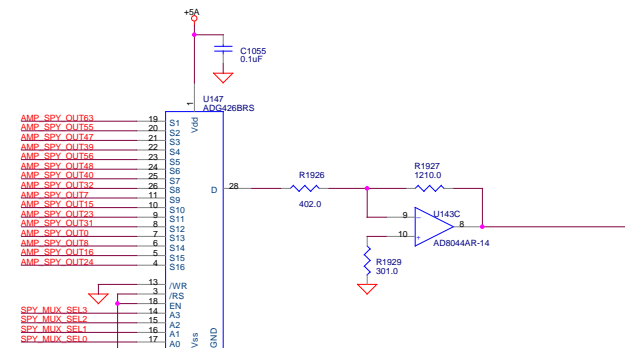
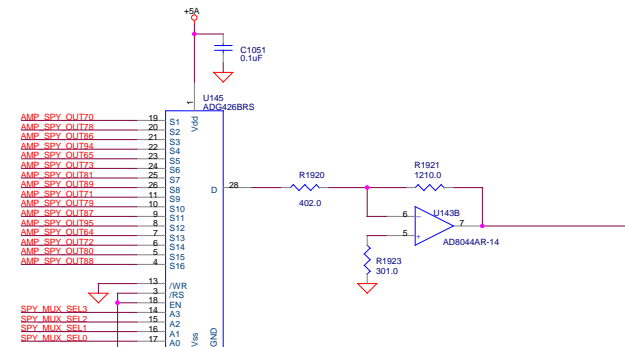
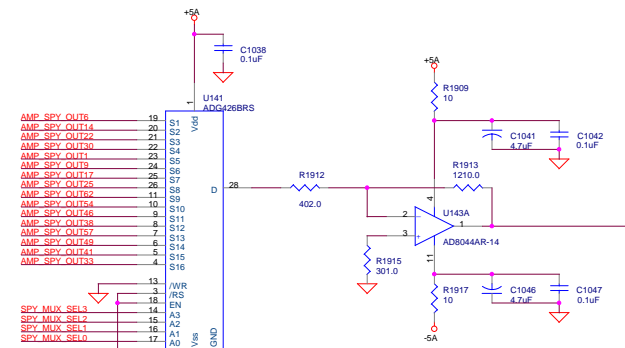
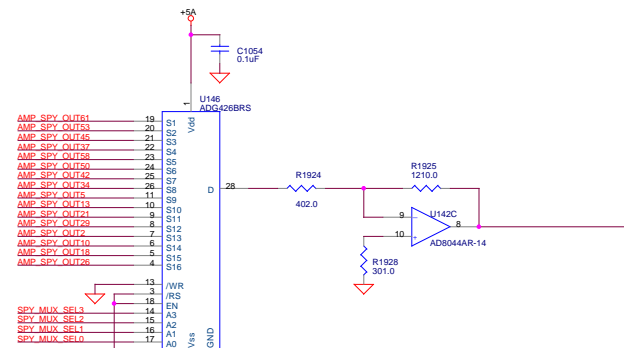
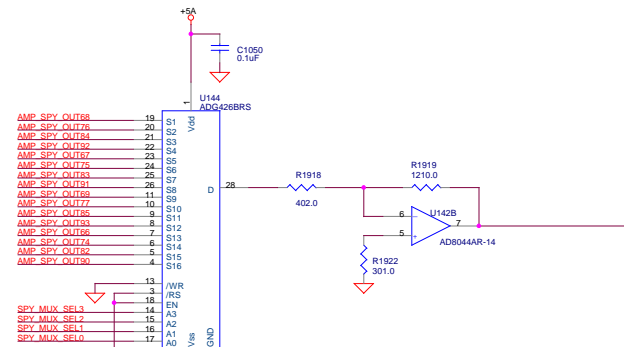
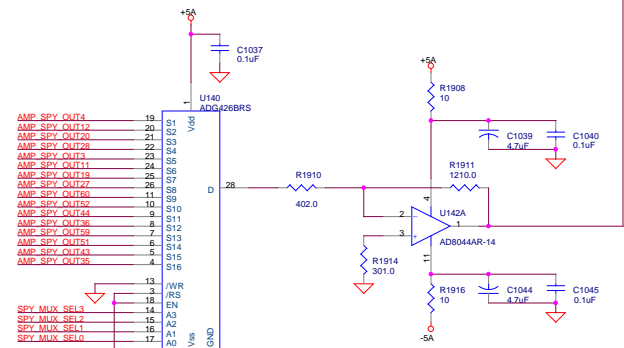
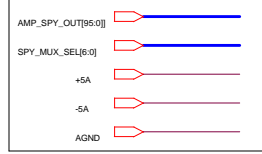


### OUTPUTS



- CHANGES FROM REV0**
- ADDED PSEUDO TRIGGER OUTPUTS
  - REMOVED BCLK\_FF
  - PLACED JTAG HEADER ON THIS PAGE
  - ADDED 33 OHM SOURCE TERMINATION TO ALL CLOCK LINES
  - CORRECTED PART NUMBER FOR 74AHCT541
  - ADDED ADDITIONAL SERIES TERM ON INPUT DRIVER

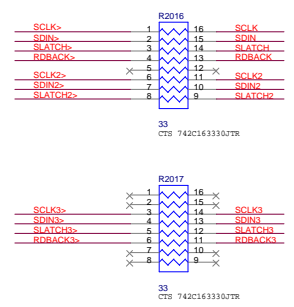
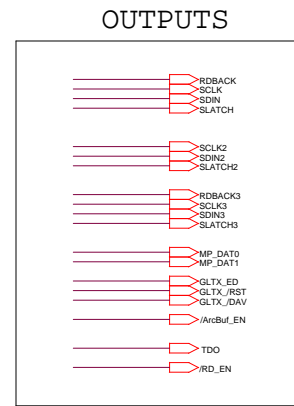
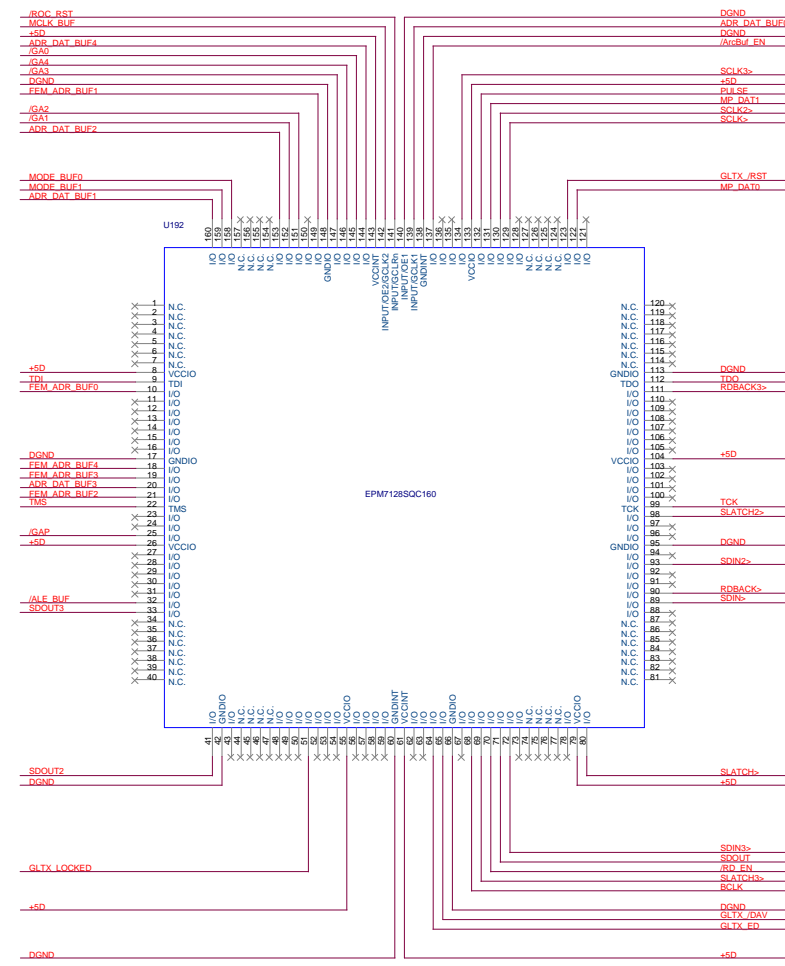
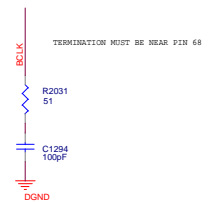
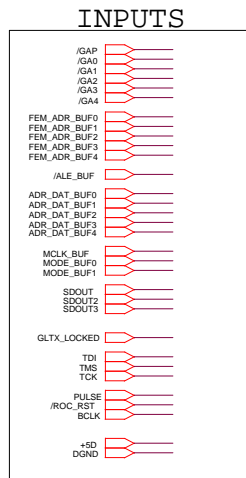
# INPUTS



**CHANGES FROM REV0**  
NO CHANGES

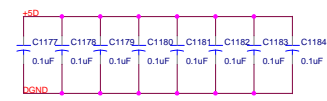
**Phenix MuID ROC**  
Oak Ridge National Lab  
Instrumentation and Controls Division

## ADDRESS DECODER FPGA

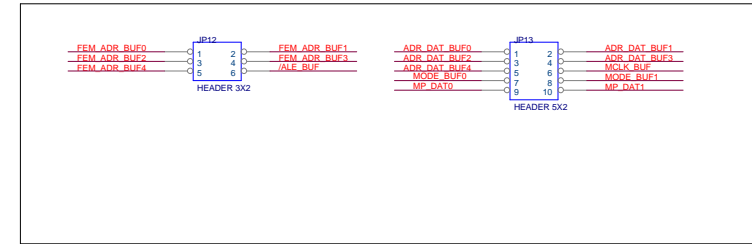


Place bypass caps next to each VCC pin for every IC

Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.

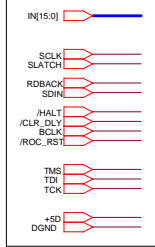


### TEST HEADERS

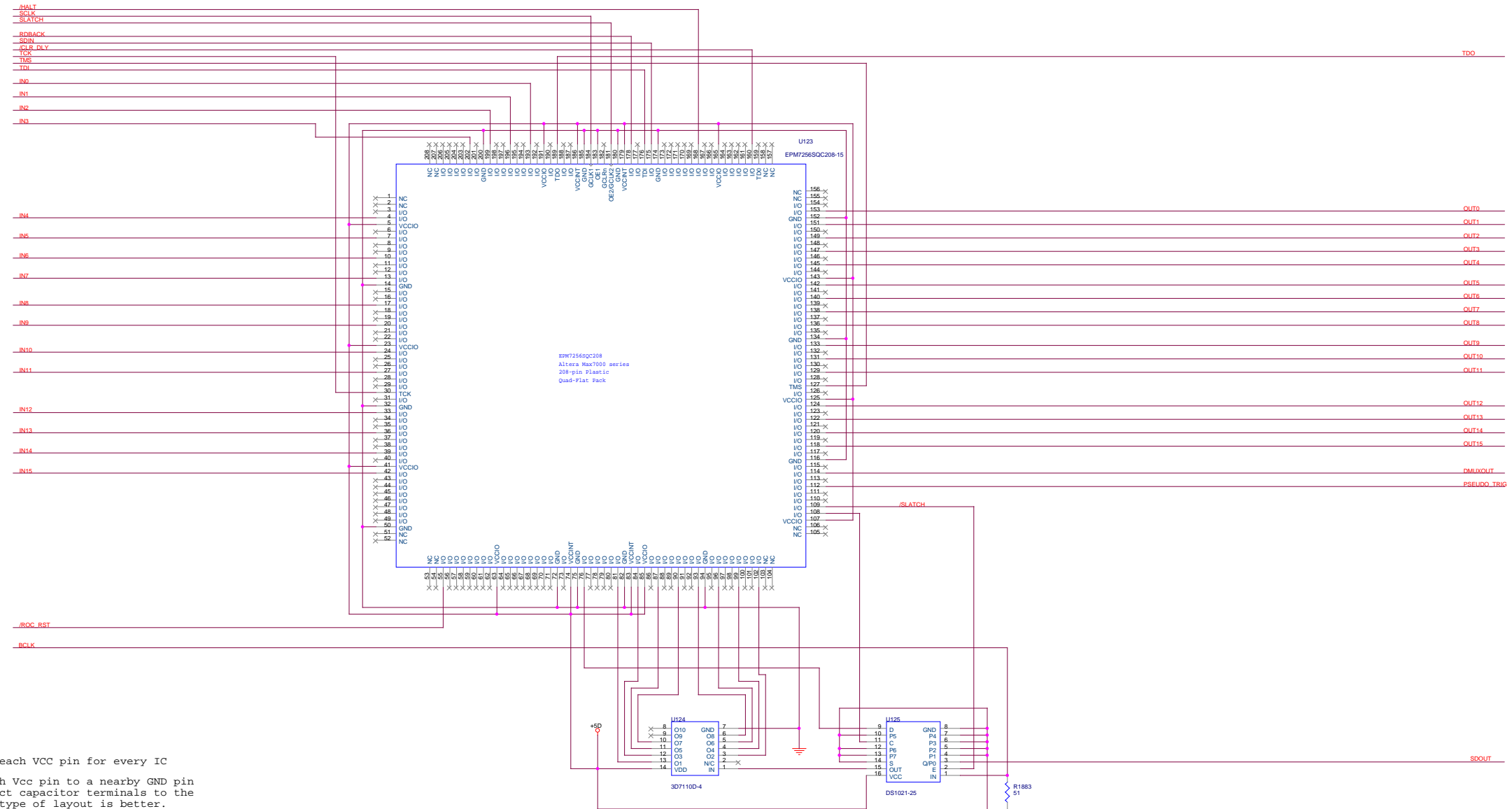
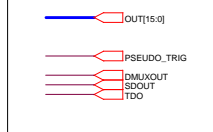


- CHANGES FROM REV0**
1. REMOVED TRI\_STATE DRIVER AND ADDED SERIES TERMINATIONS
  2. ADDED PULSE, /ROC\_RESET, AND BCLK TO EPM7128
  3. REMOVED CONNECTIONS TO RDBACK2 AND /RRESET2

### INPUTS

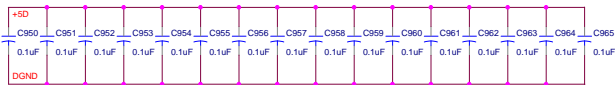


### OUTPUTS



Place bypass caps next to each VCC pin for every IC

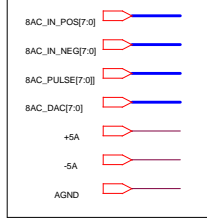
Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.



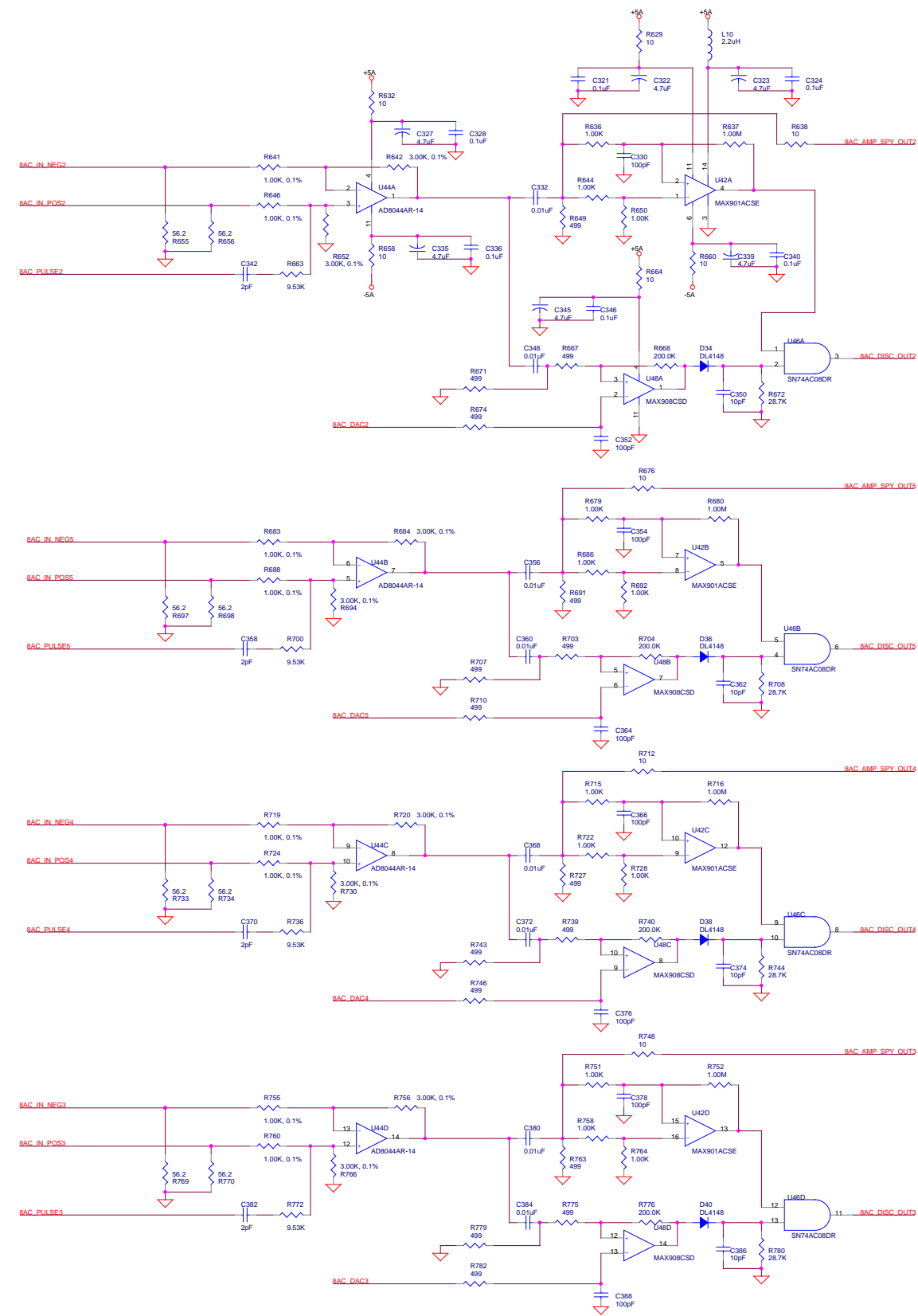
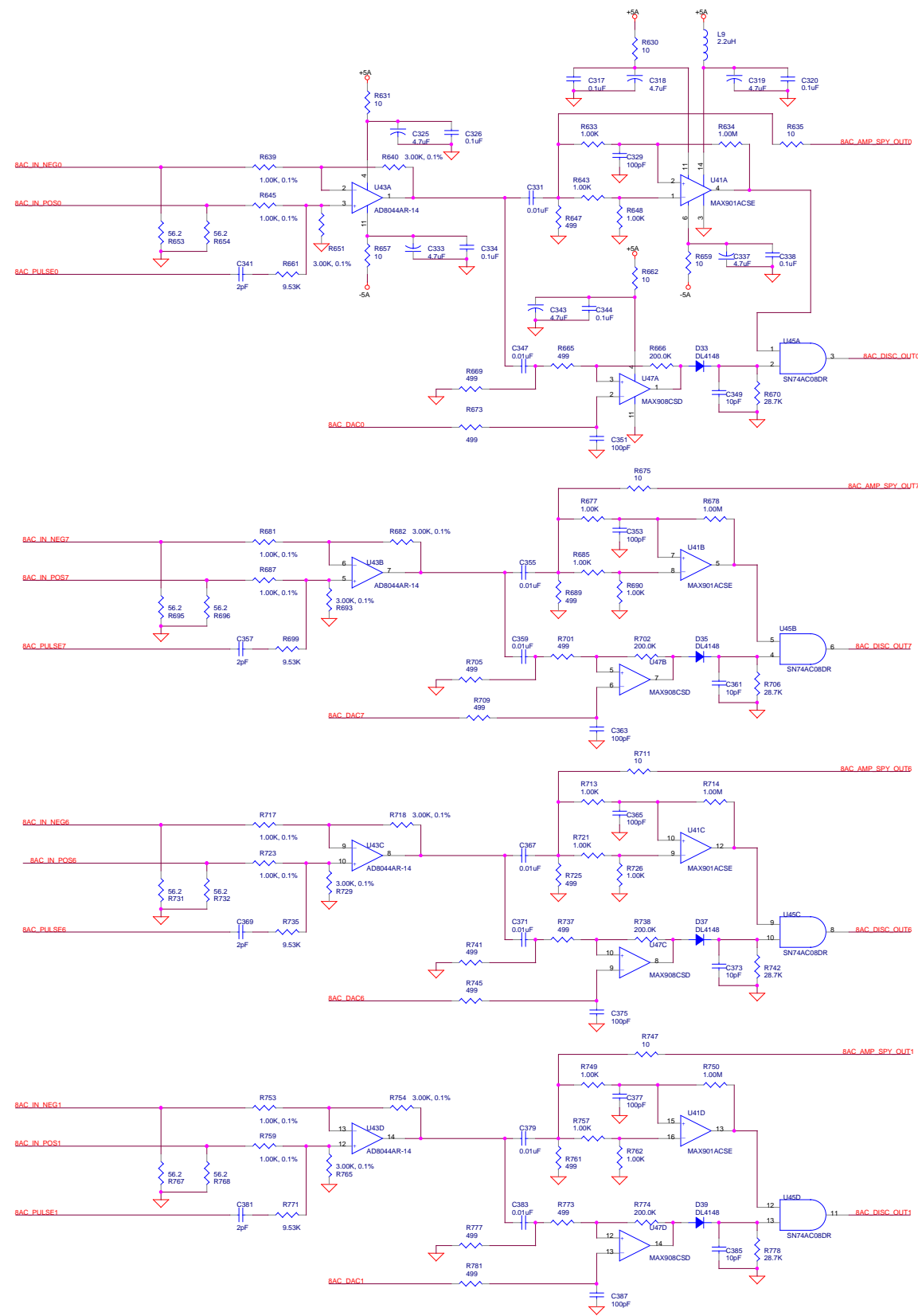
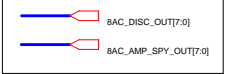
- CHANGES FROM REV0**
1. CHANGED BCLK TERMINATION
  2. 1021 CHIP SCLK CONNECTED TO CONDITIONED SIGNAL TO ALLOW SERIAL READBACK
  3. REMOVED CLR\_SRL SIGNAL
  4. REMOVED PULL-UP RESISTORS FROM DELAY CHIP



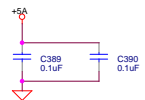
### INPUTS



### OUTPUTS

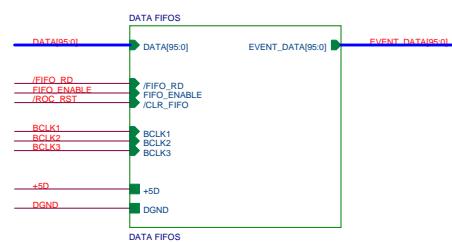
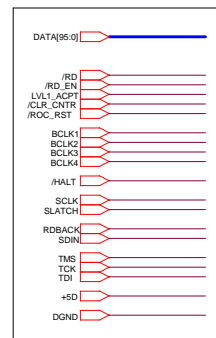


BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS

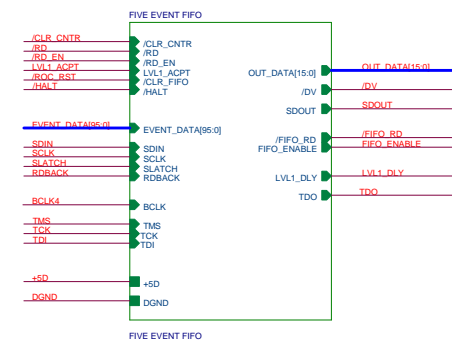
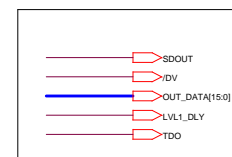


- CHANGES FROM REV0**
1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF
  2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

### INPUTS

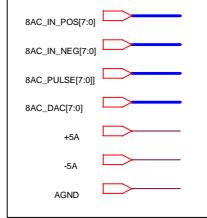


### OUTPUTS

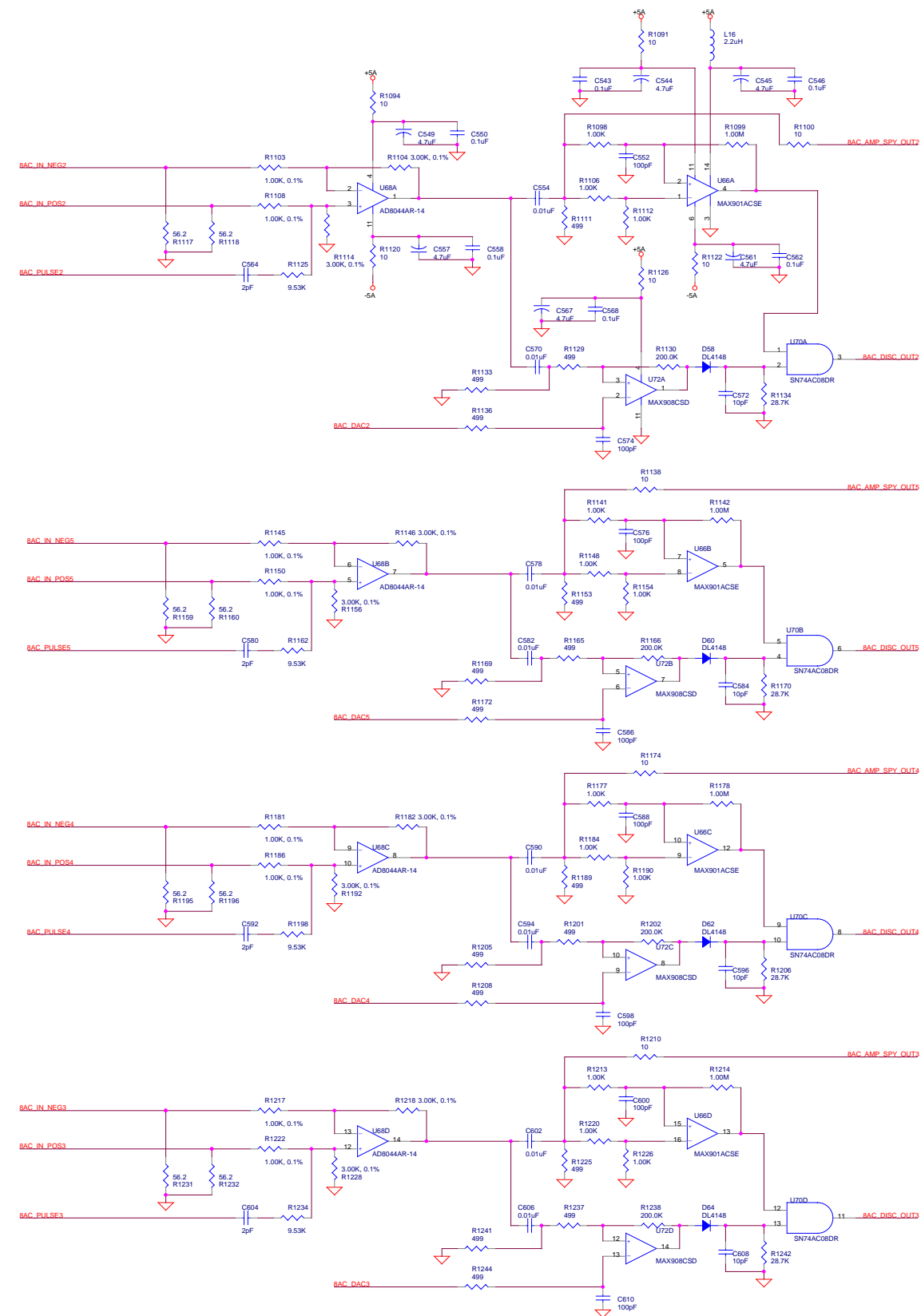
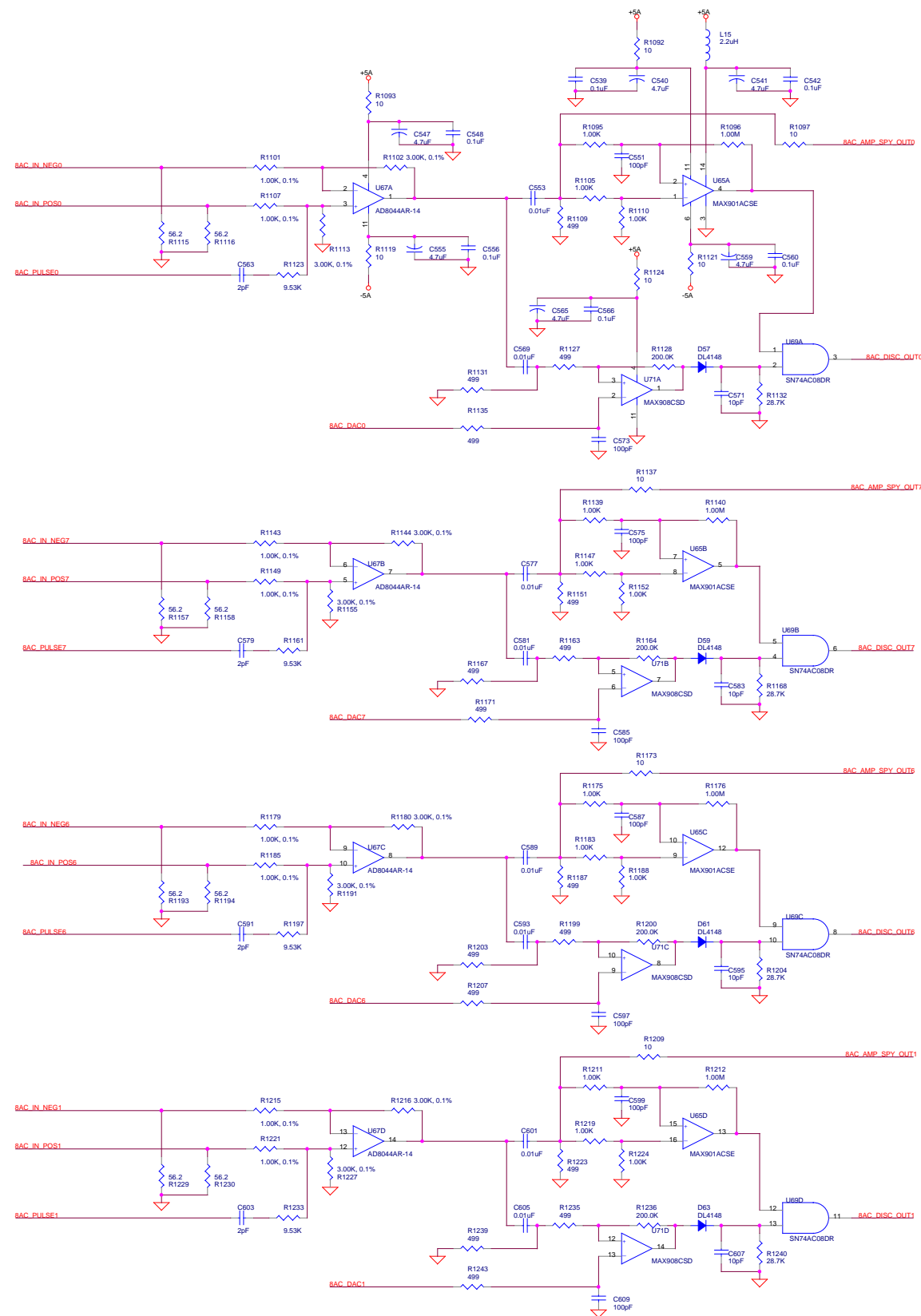


**CHANGES FROM REV0**  
 1. CHANGED TO USE JTAG HEADER ON I/O PAGE

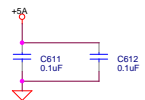
### INPUTS



### OUTPUTS



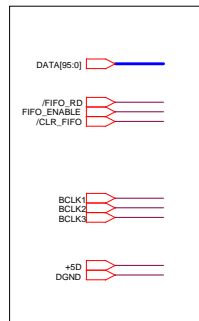
BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS



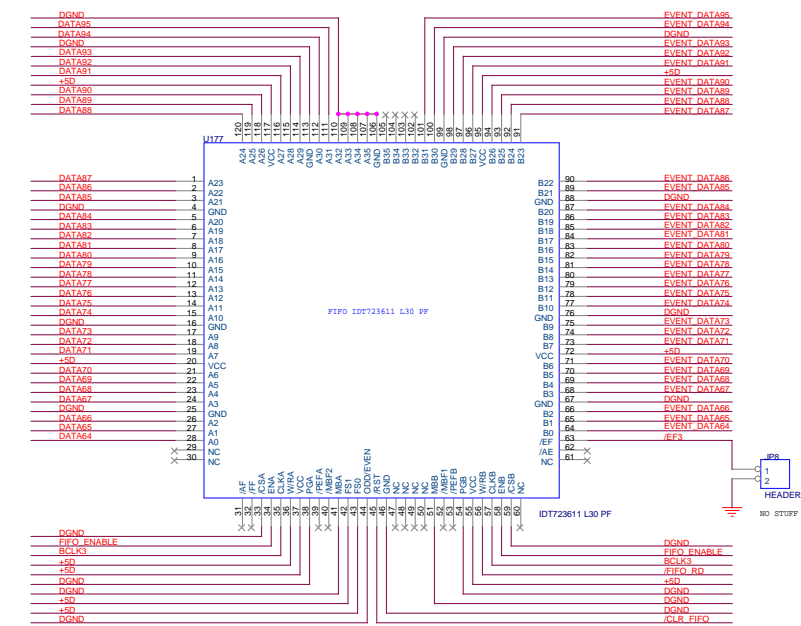
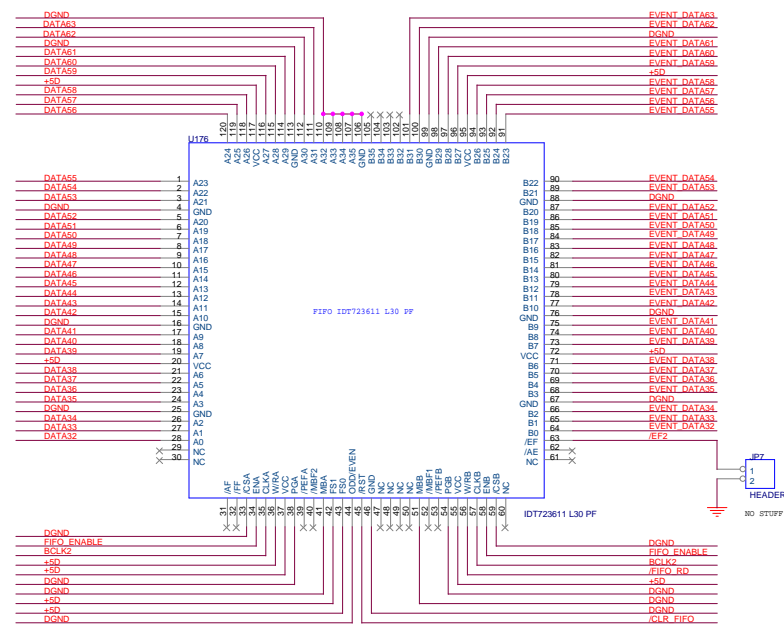
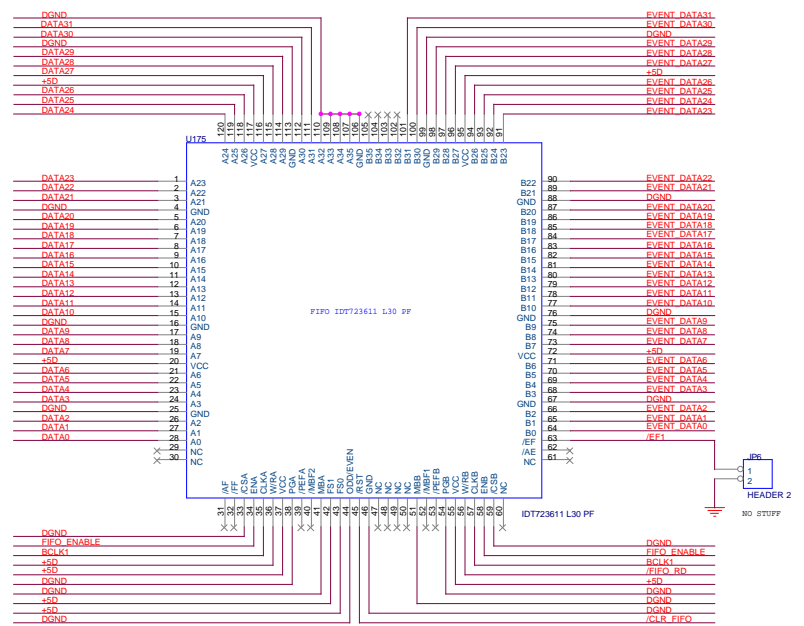
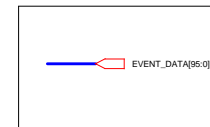
- CHANGES FROM REV0**
1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF
  2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

# DATA FIFOS AND TEST HEADERS

## INPUTS



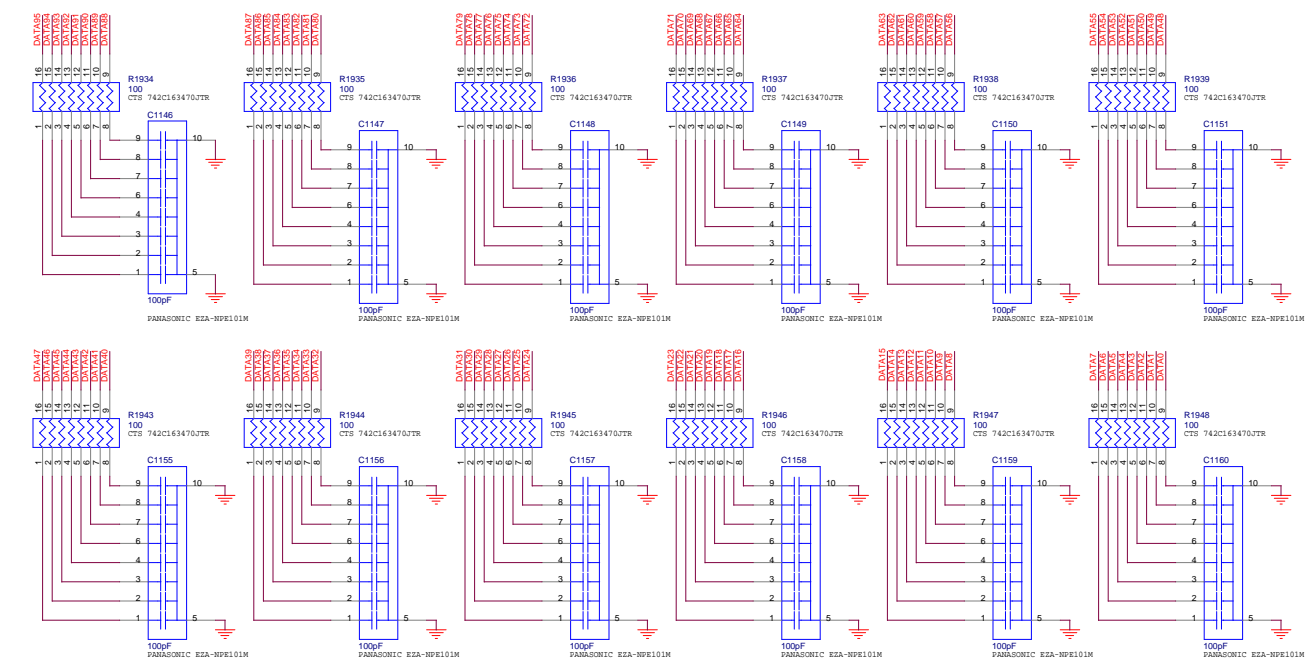
## OUTPUTS



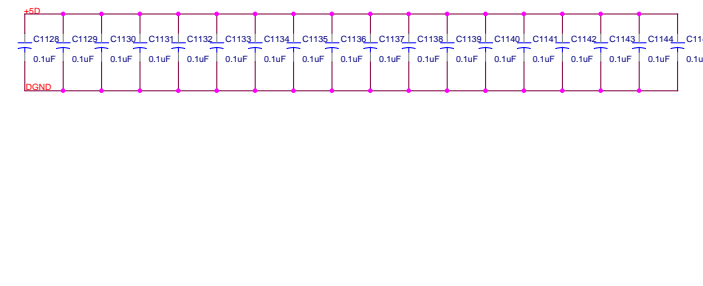
## PARALLEL RC TERMINATION

Use parallel RC termination in parallel with lines DATA0-DATA95 and BCLK. This is because the traces from Delay Mux FPGA will be long (>7.5 inches). Put a resistor and cap to DGND in parallel with each input pin. R = line impedance is assumed to be 100-ohms. Change if the actual line impedance differs. C > 100pF.

\*\*Place Resistor/Cap as close to input pin as possible. \*\*  
\*\* One BCLKn Termination PER CHIP! \*\*

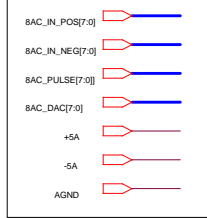


Place bypass caps next to pins 20, 37, 55, 72, 95, 117 for every IC  
Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.

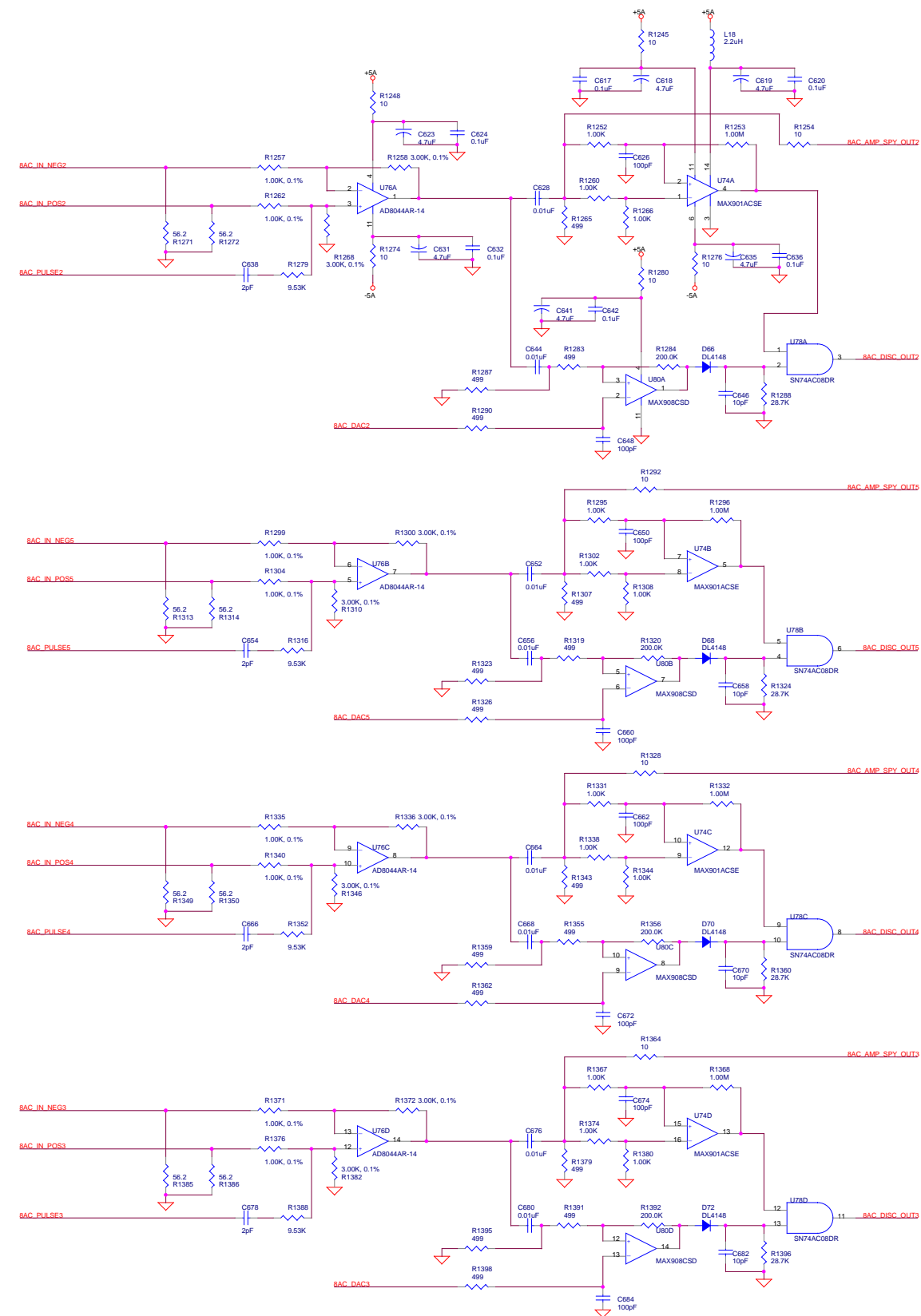
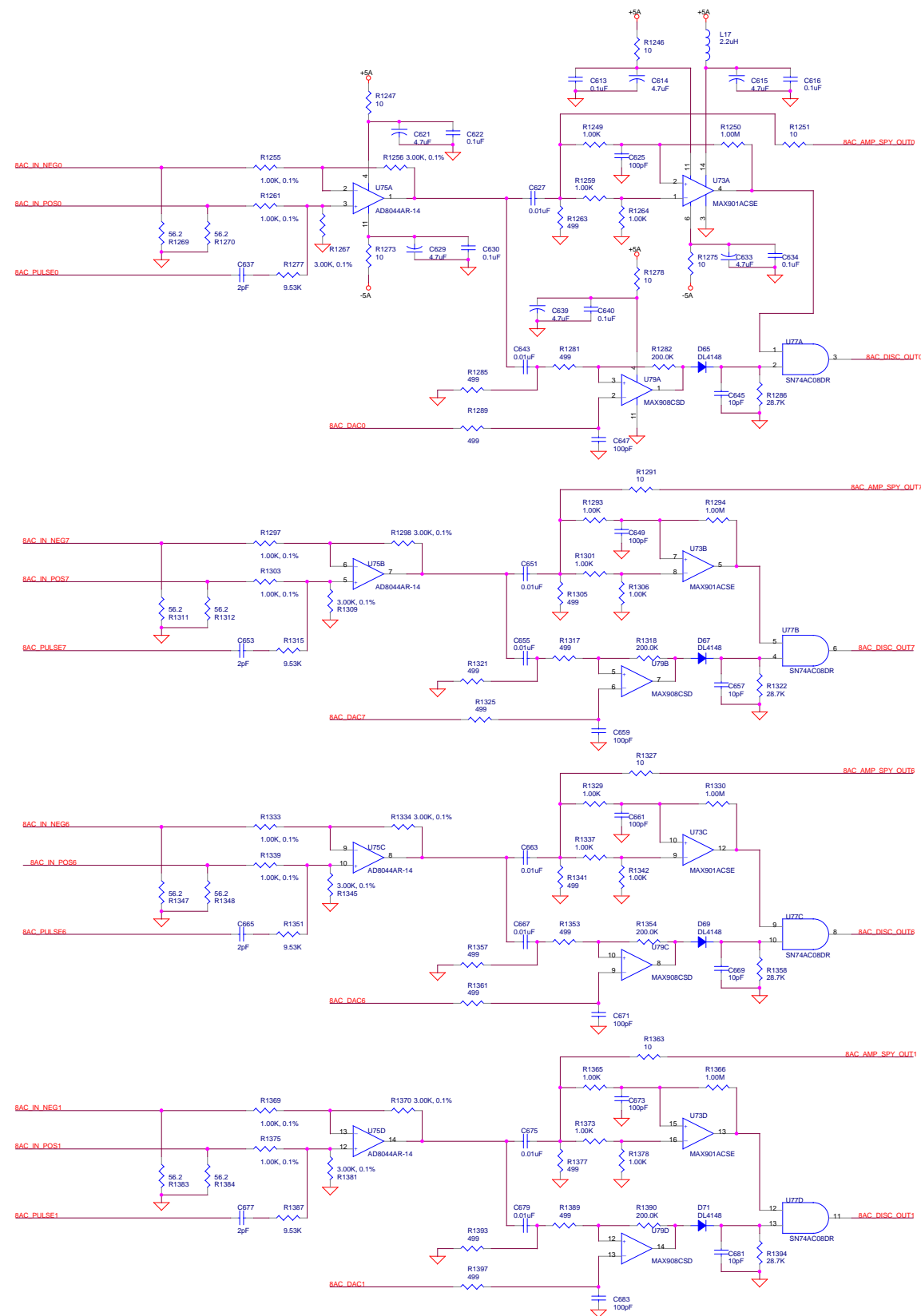
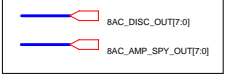


- CHANGES FROM REV0**
1. CHANGED BCLK TO BCLK1 ON TEST HEADER
  2. CHANGED VALUE OF TERMINATION RESISTORS AND CAPS

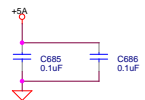
### INPUTS



### OUTPUTS

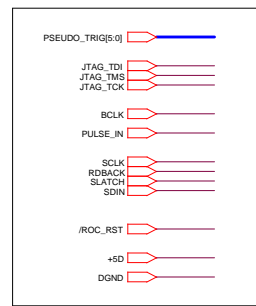


BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS

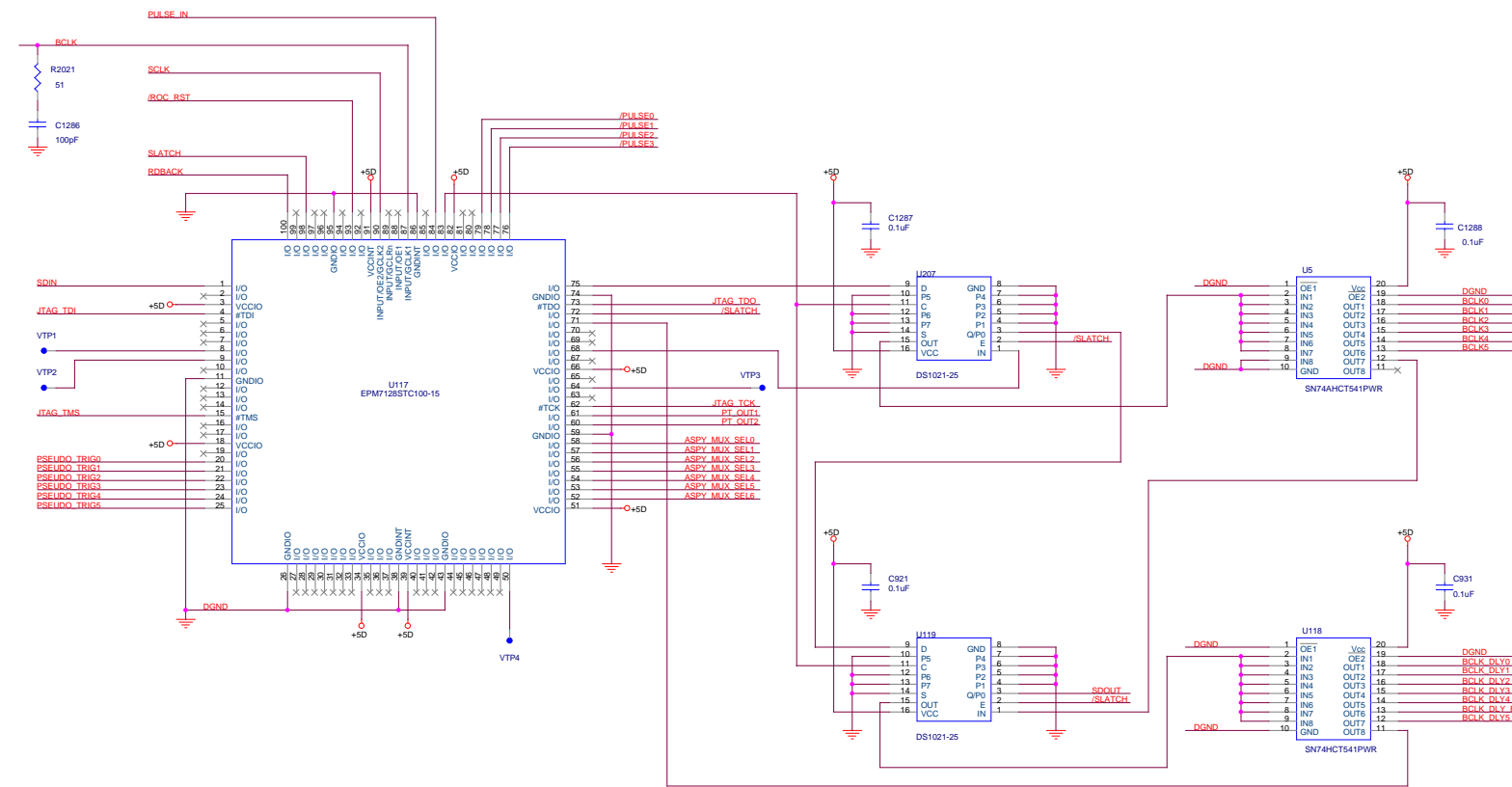
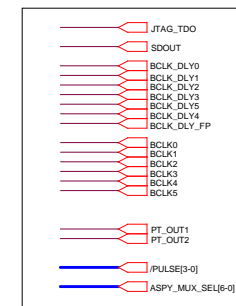


**CHANGES FROM REV0**  
 1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF  
 2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

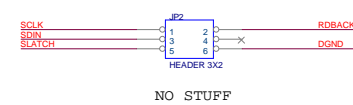
### INPUTS



### OUTPUTS

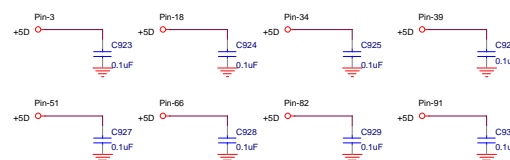


### SERIAL DOWNLOAD



### BY-PASS CAPACITORS FOR Misc Serial FPGA

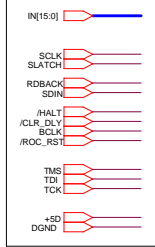
Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.



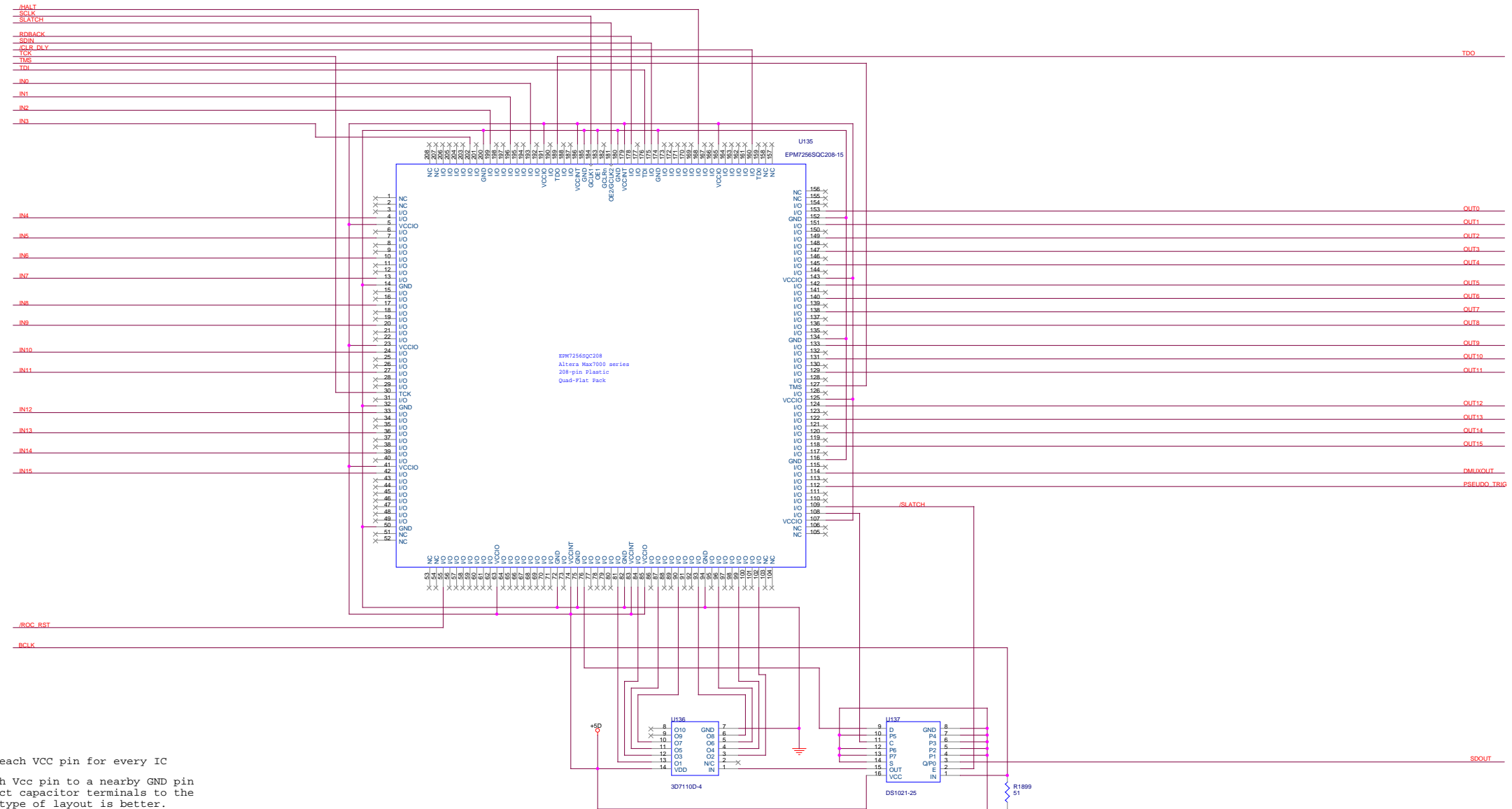
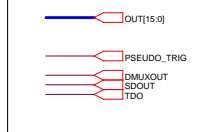
- CHANGES FROM REV0**
1. ADDED BCLK\_DLY5
  2. ADDED NO STUFF TO HEADER
  3. SCLK TO DS1021 CONDITIONED TO ALLOW READBACK
  4. REMOVED /SRESET
  5. ADDED DELAY TO BCLKx SIGNALS
  6. ADDED BCLK TERMINATION

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Oak Ridge National Lab  
Instrumentation and Controls Division

### INPUTS

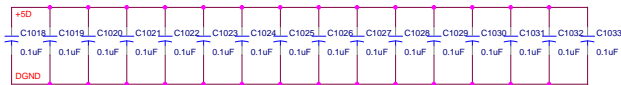


### OUTPUTS



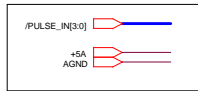
Place bypass caps next to each VCC pin for every IC

Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.

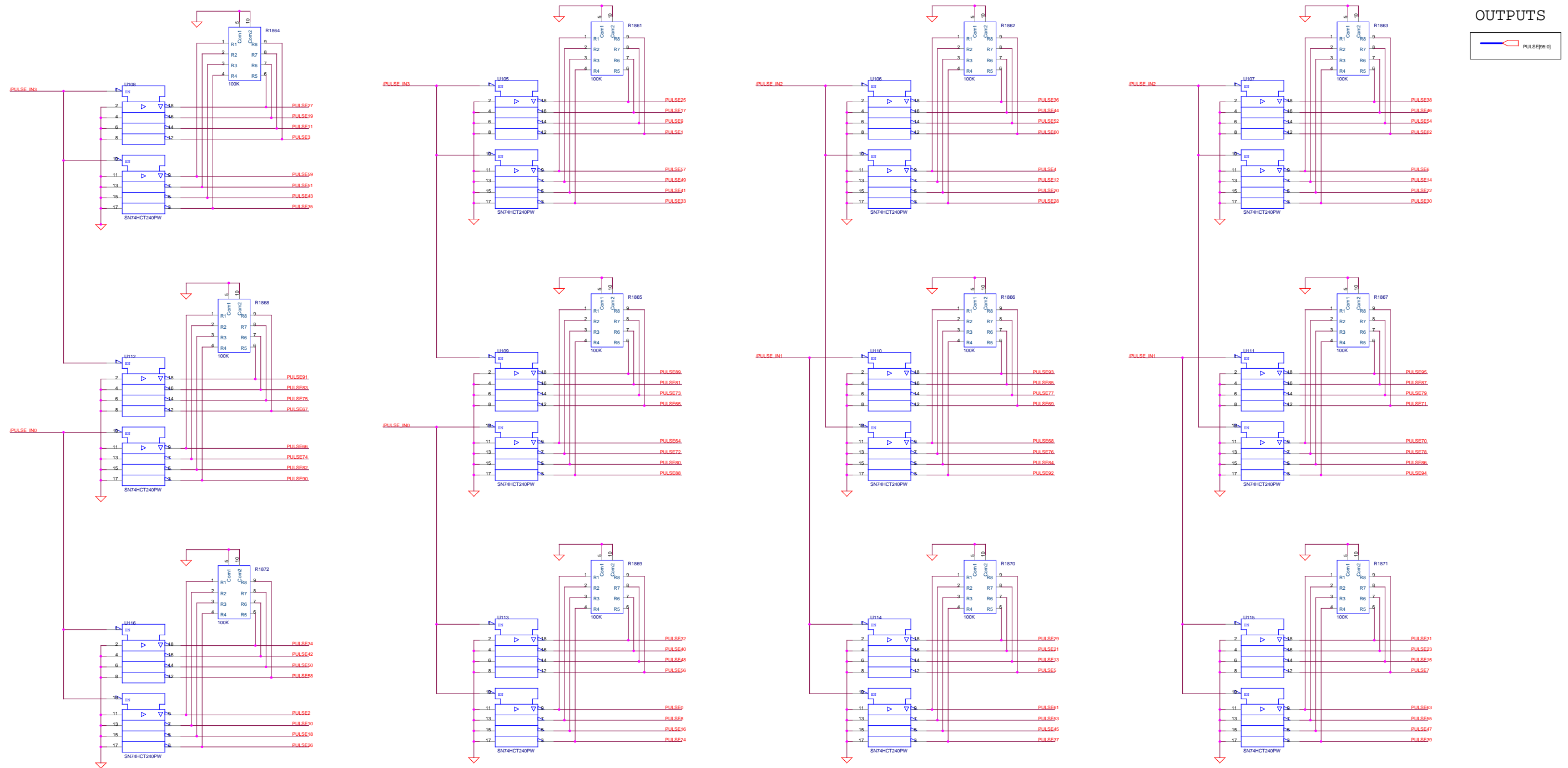
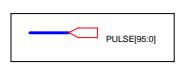


- CHANGES FROM REV0**
1. CHANGED BCLK TERMINATION
  2. 1021 CHIP SCLK CONNECTED TO CONDITIONED SIGNAL TO ALLOW SERIAL READBACK
  3. REMOVED CLR\_SRL SIGNAL
  4. REMOVED PULL-UP RESISTORS FROM DELAY CHIP

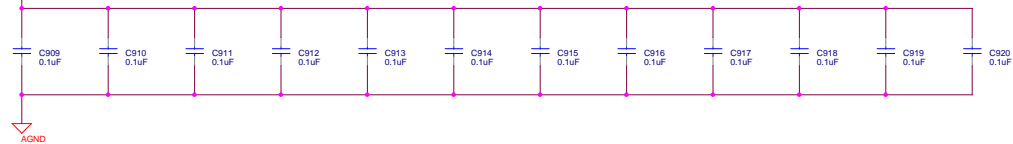
**INPUTS**



**OUTPUTS**



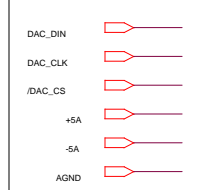
**BYPASS CAPS BETWEEN PINS 10 AND 20 OF SN74HCT240PW CHIPS**



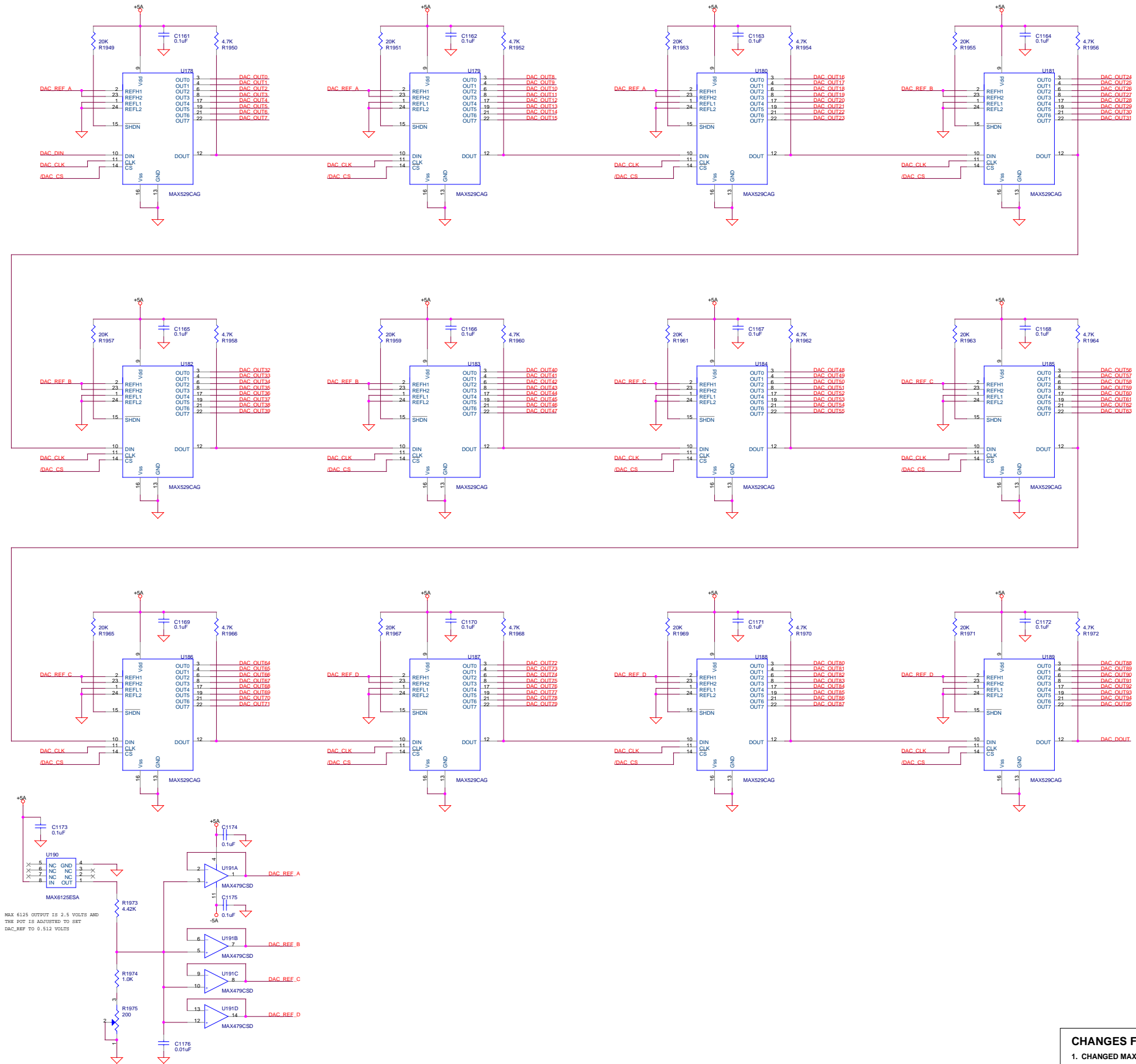
**CHANGES FROM REV0**  
 1. PULSE DRIVER CHIPS CHANGED FROM 74ACT240 TO 74HCT240 TO REDUCE PULSE RISE TIME  
 2. MOVED ALL COMPONENTS TO ANALOG POWER AND GROUND



### INPUTS



### OUTPUTS



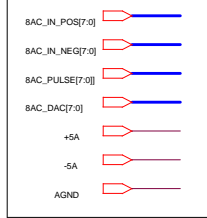
MAX 6125 OUTPUT IS 2.5 VOLTS AND THE POT IS ADJUSTED TO SET DAC\_REF TO 0.512 VOLTS

**CHANGES FROM REV0**  
 1. CHANGED MAX6125 TO SO PACKAGE FOR AVAILABILITY

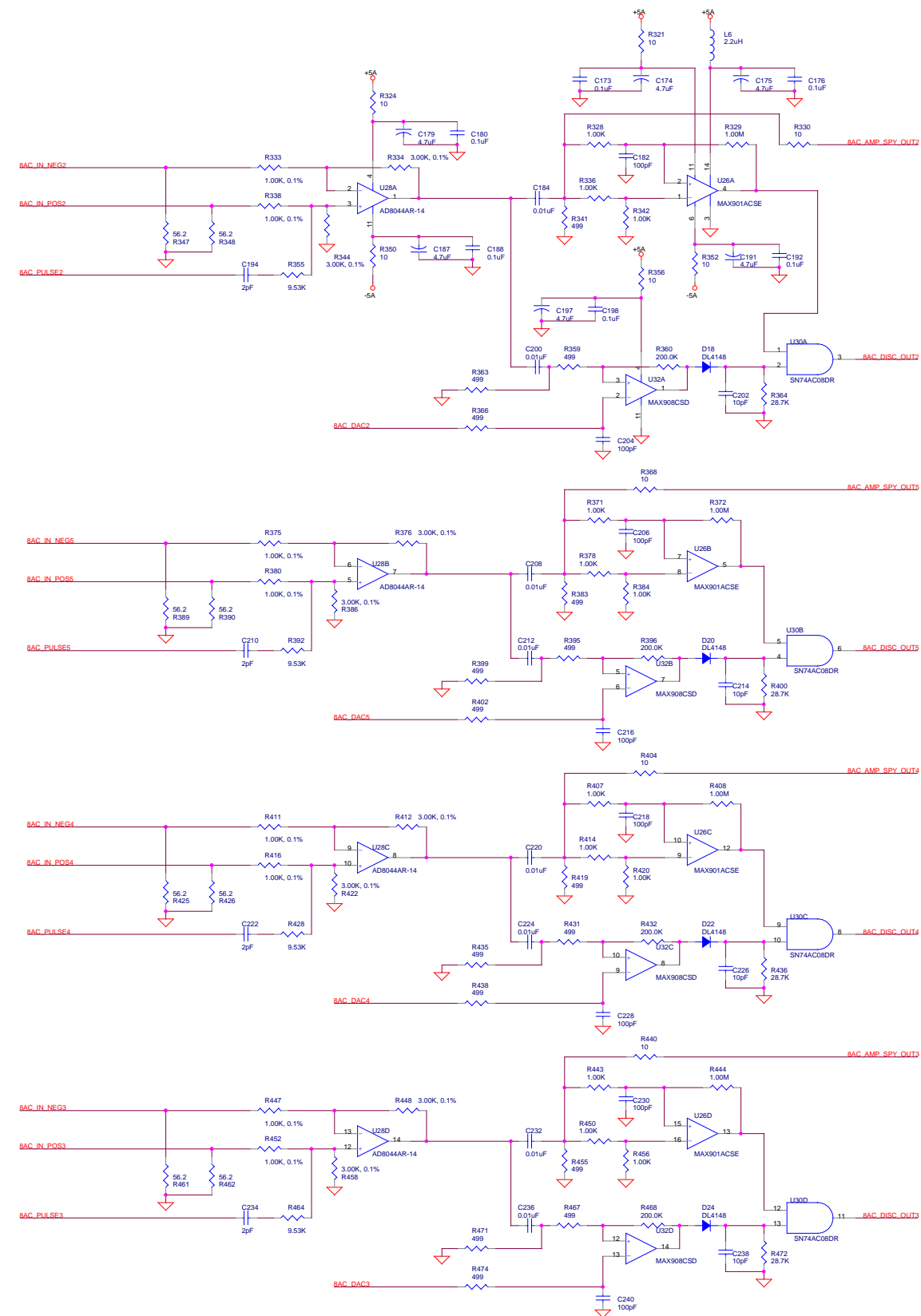
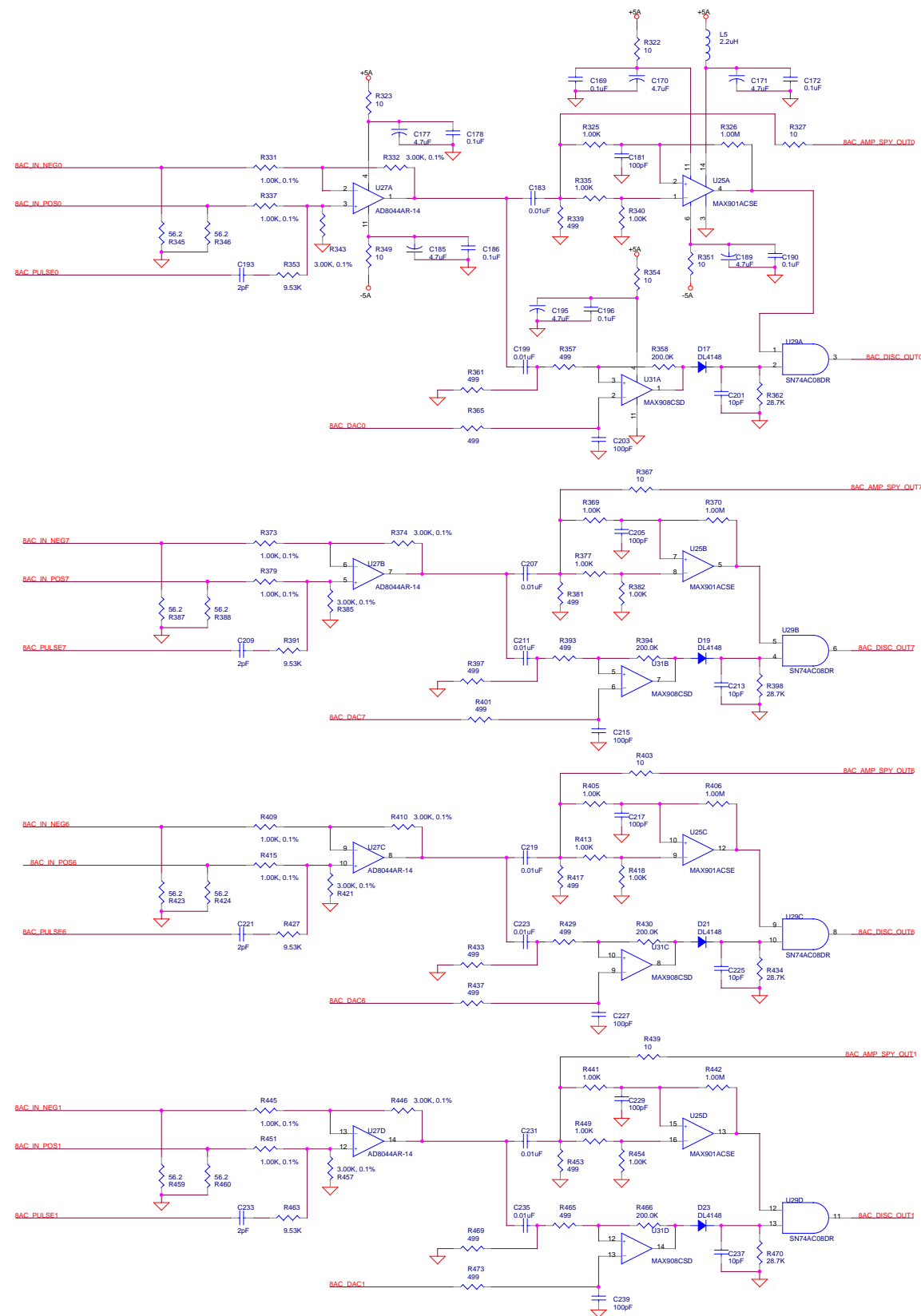
Phenix MuID ROC  
 Oak Ridge National Lab  
 Instrumentation and Controls Division

File	DAC5	
Date	Document Number	Rev
D	5.3.13.002-0313-191	
Date	Tuesday, October 03, 2000	Sheet 26 of 34

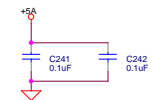
### INPUTS



### OUTPUTS

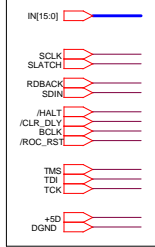


BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS

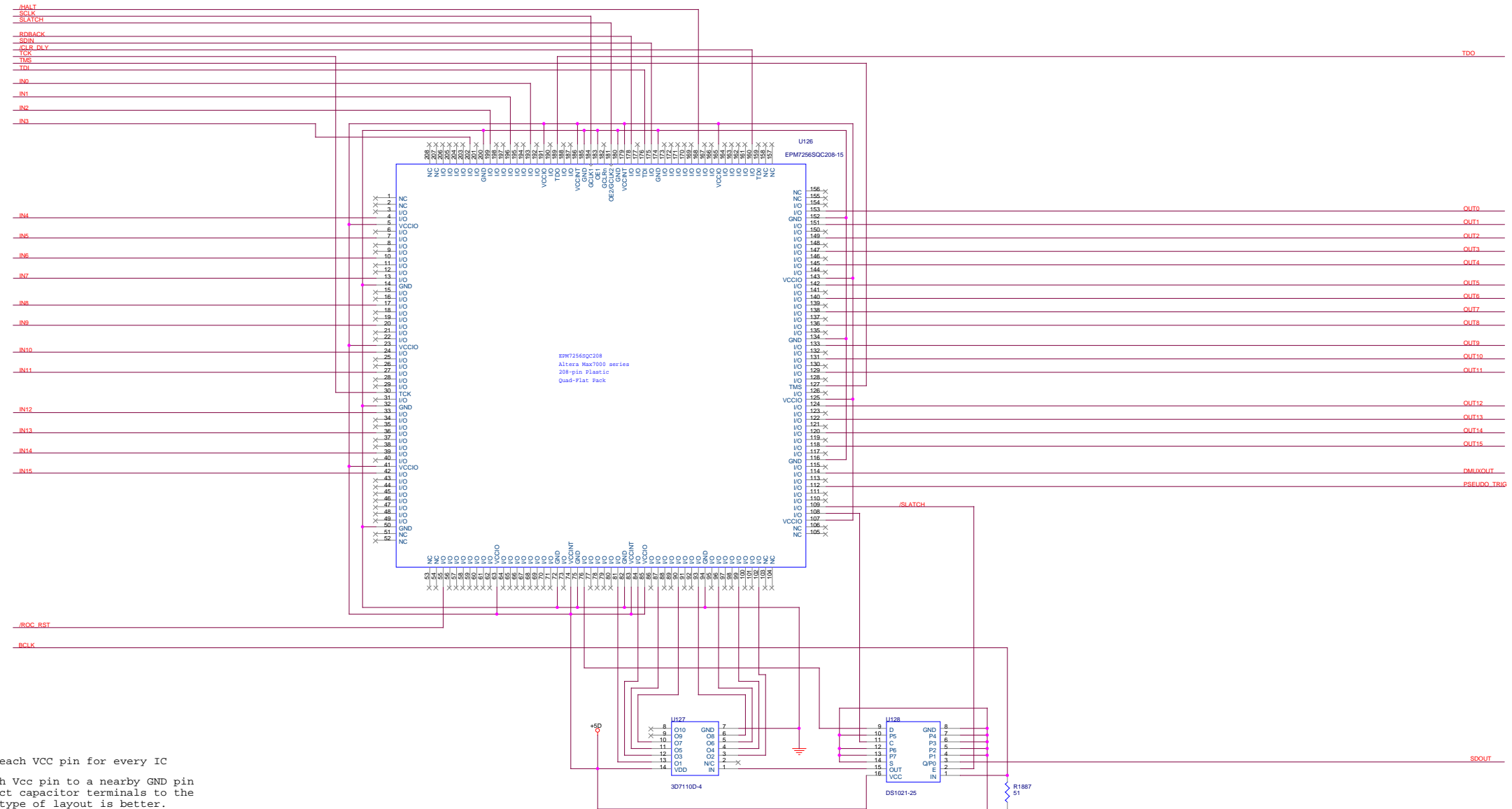
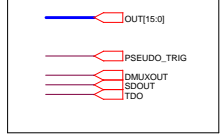


**CHANGES FROM REV0**  
 1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF  
 2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

### INPUTS

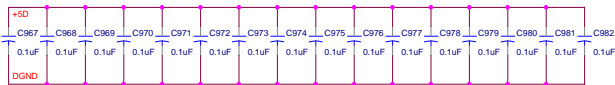


### OUTPUTS



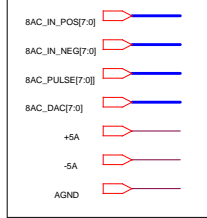
Place bypass caps next to each VCC pin for every IC

Place bypass caps from each Vcc pin to a nearby GND pin on the chip and then connect capacitor terminals to the Vcc and DGND planes. This type of layout is better.

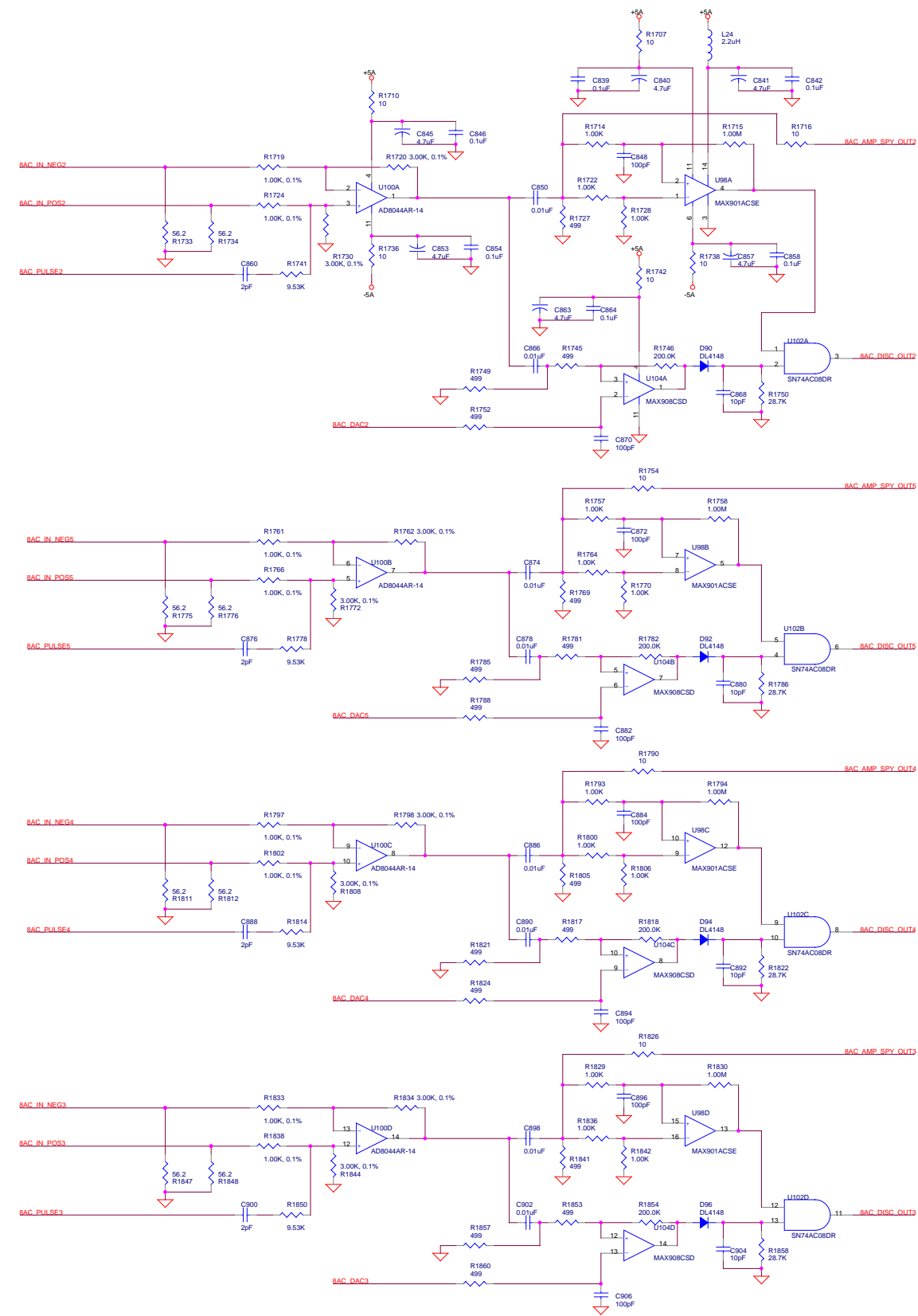
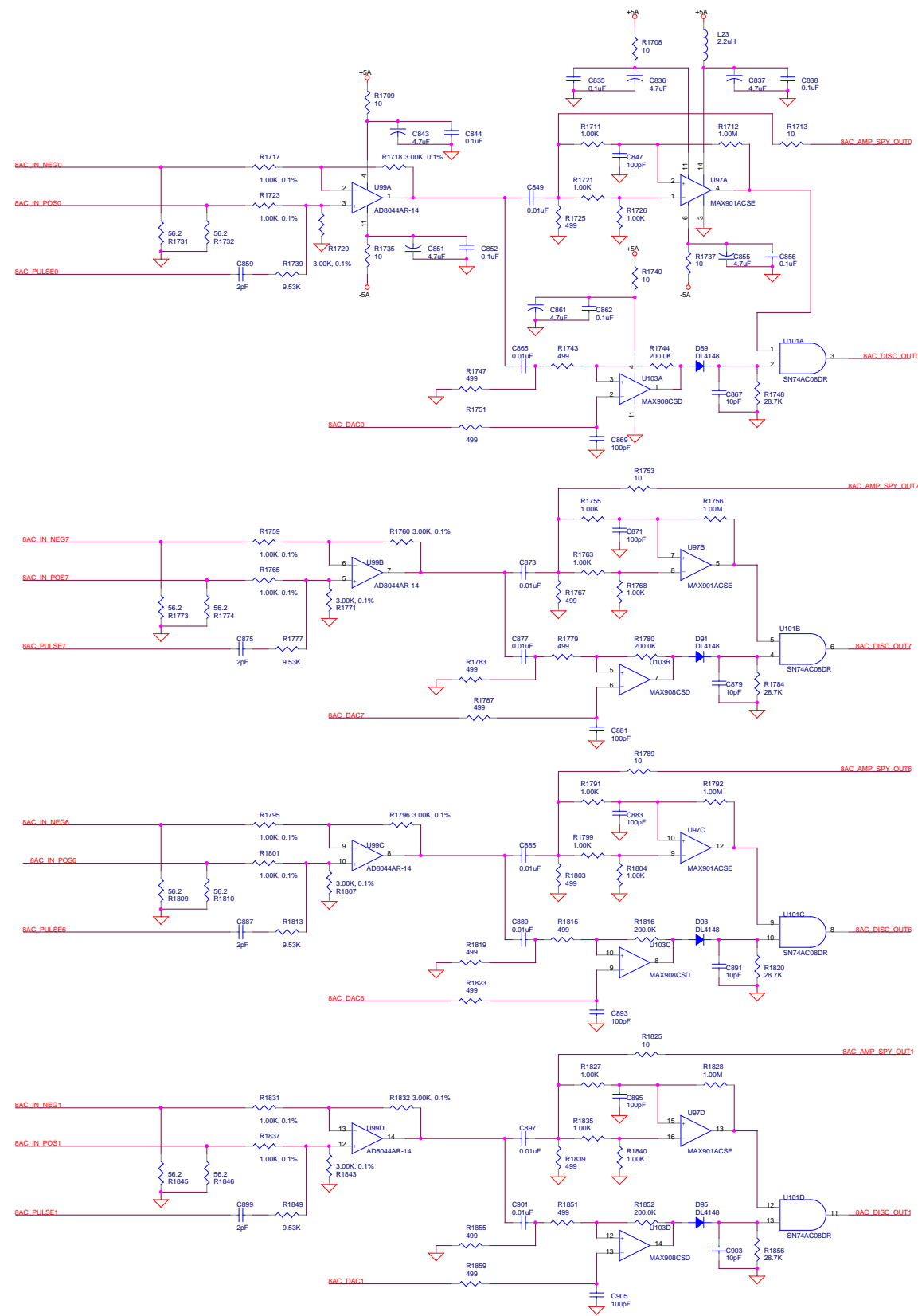


- CHANGES FROM REV0**
1. CHANGED BCLK TERMINATION
  2. 1021 CHIP SCLK CONNECTED TO CONDITIONED SIGNAL TO ALLOW SERIAL READBACK
  3. REMOVED CLR\_SRL SIGNAL
  4. REMOVED PULL-UP RESISTORS FROM DELAY CHIP

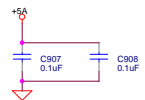
### INPUTS



### OUTPUTS

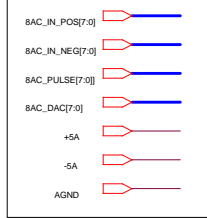


BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS

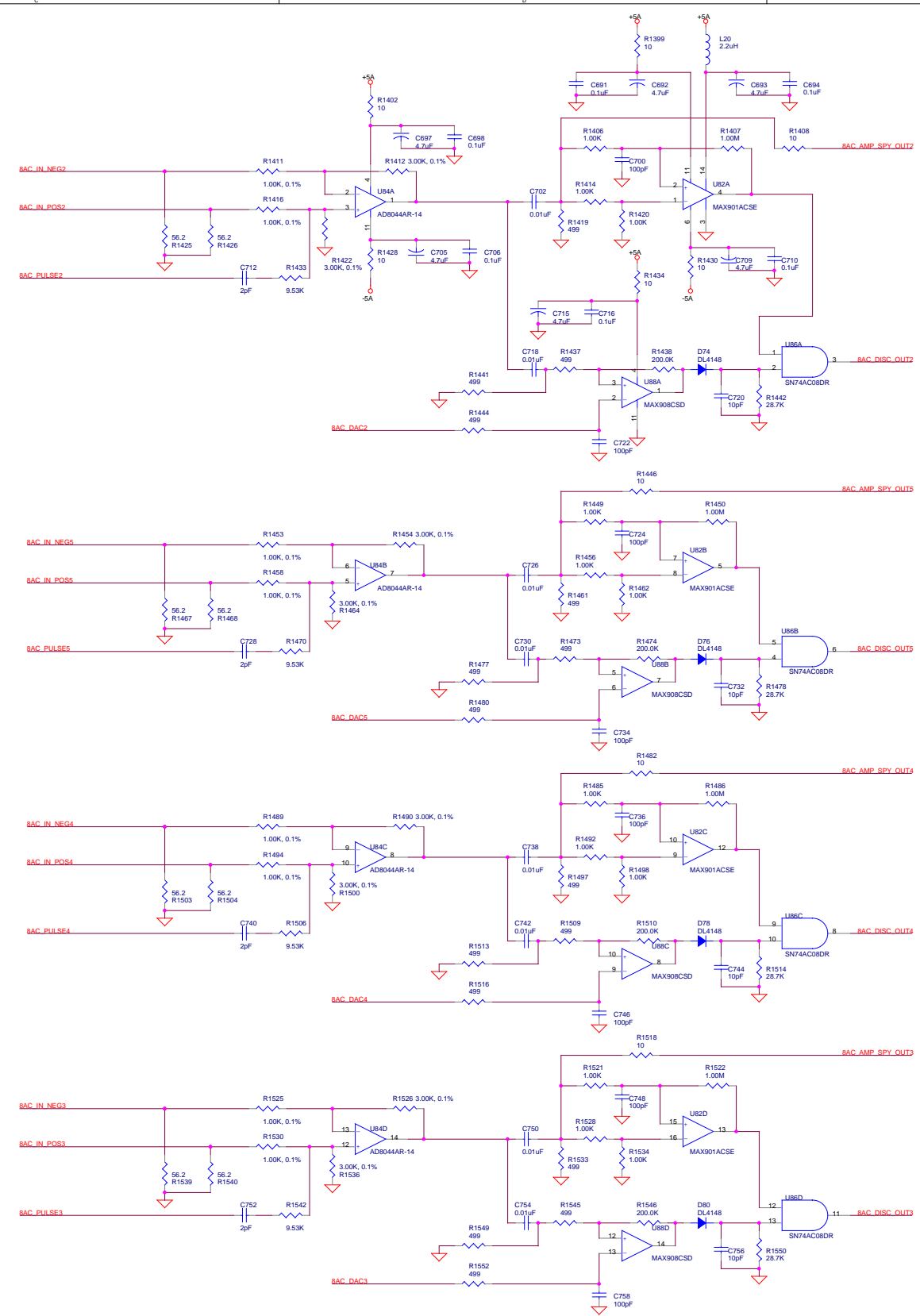
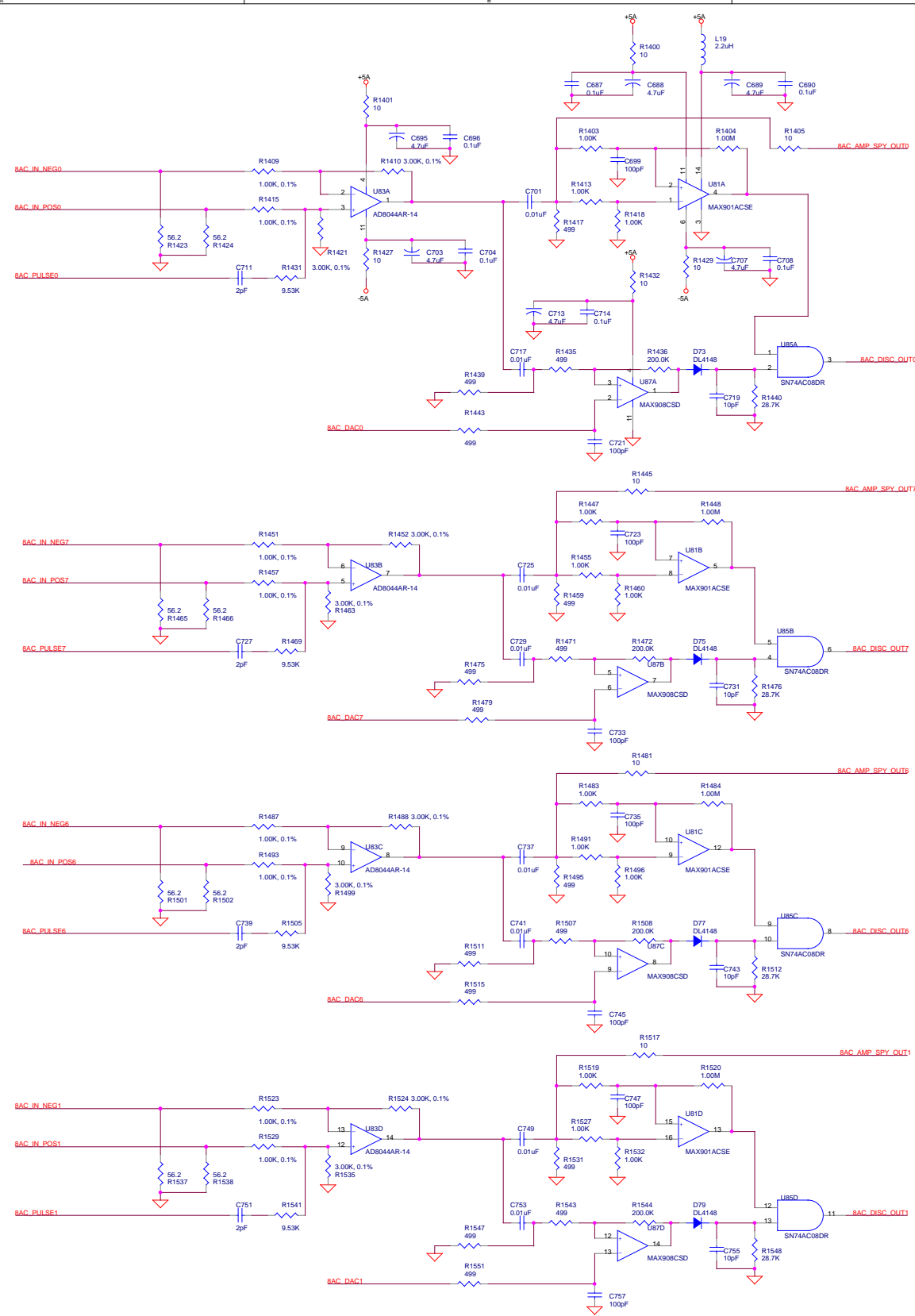
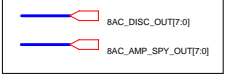


**CHANGES FROM REV0**  
 1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF  
 2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

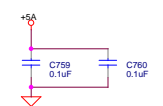
### INPUTS



### OUTPUTS

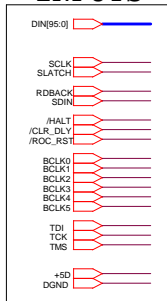


BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS

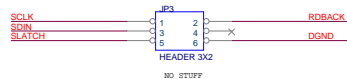


**CHANGES FROM REV0**  
 1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF  
 2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

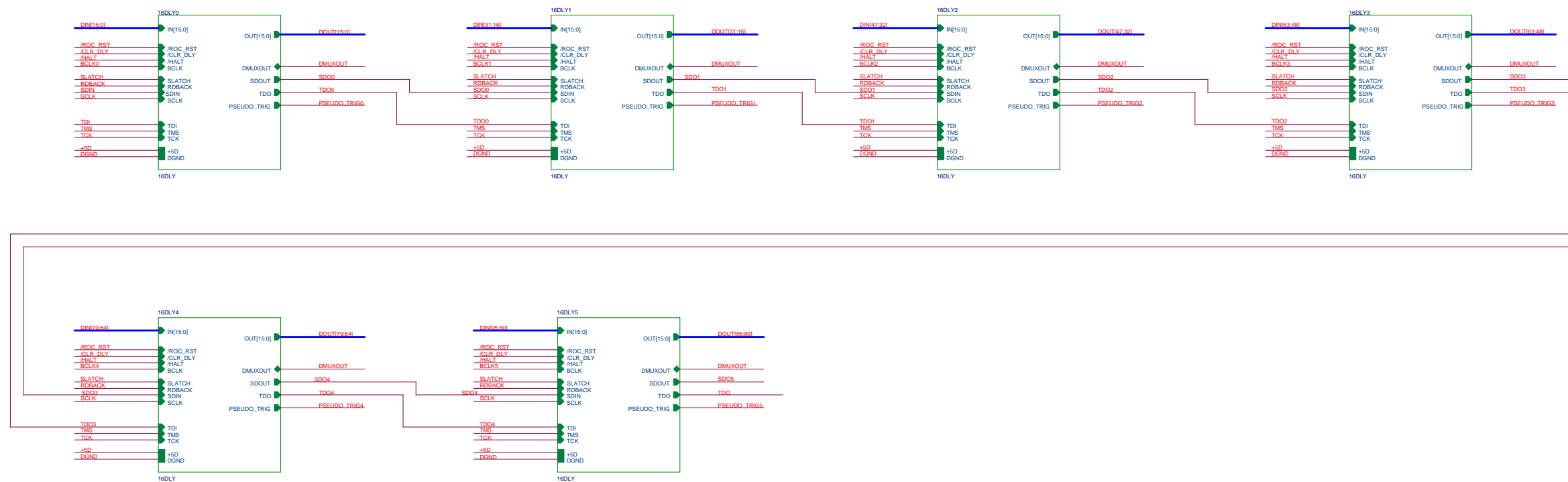
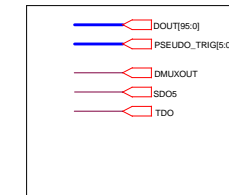
**INPUTS**



**SERIAL DOWNLOAD**

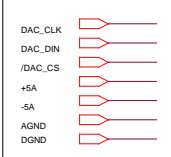


**OUTPUTS**

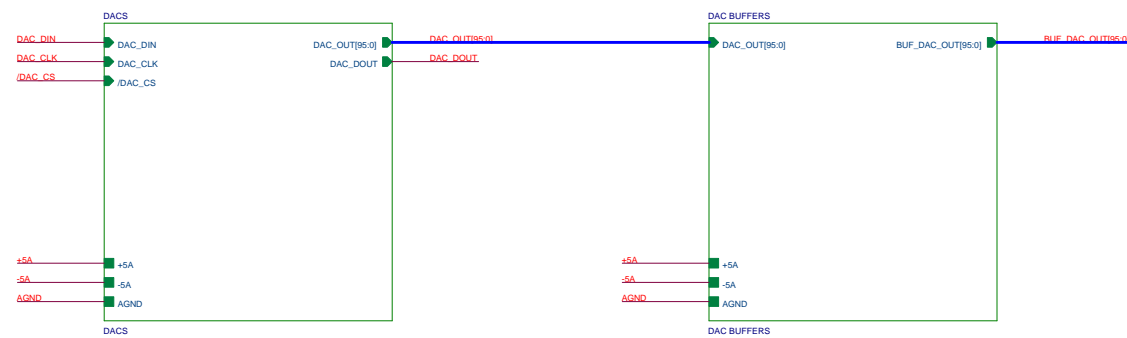
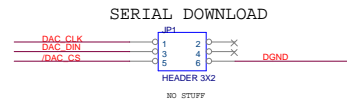
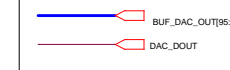


**CHANGES FROM REV0**  
 1. REMOVED CLR\_SRL  
 2. MOVED JTAG CONNECTOR TO I/O PAGE

### INPUTS



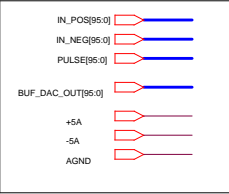
### OUTPUTS



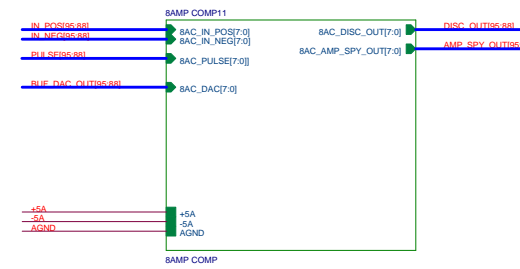
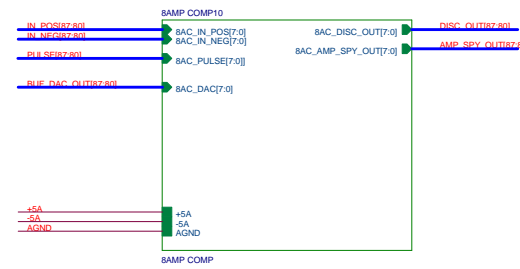
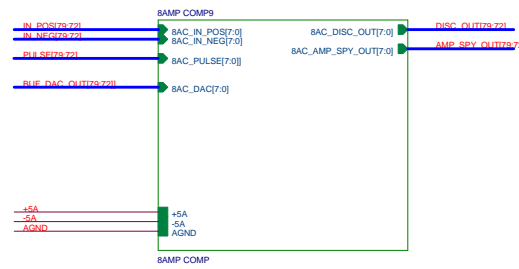
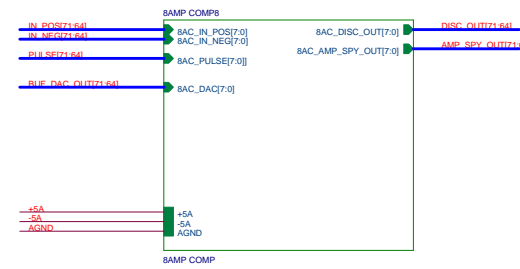
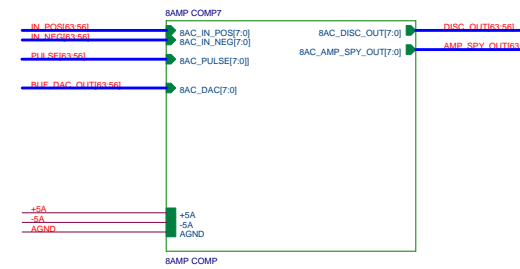
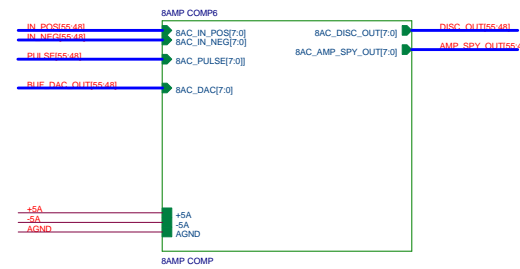
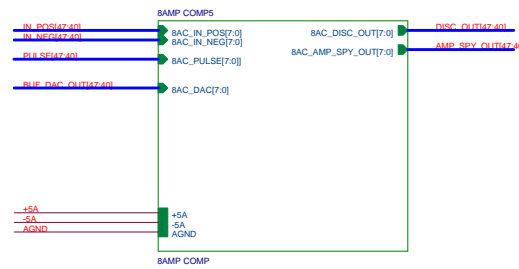
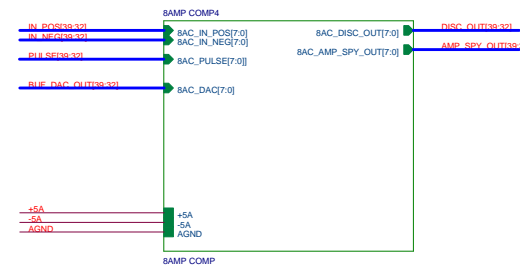
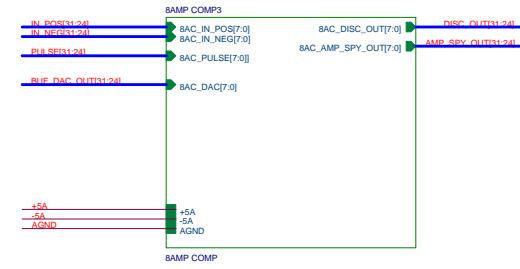
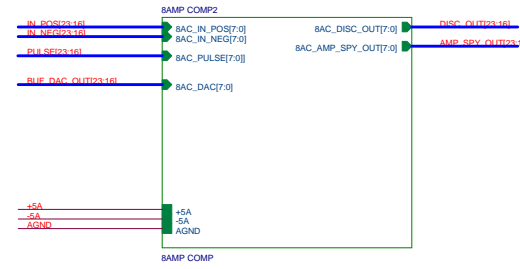
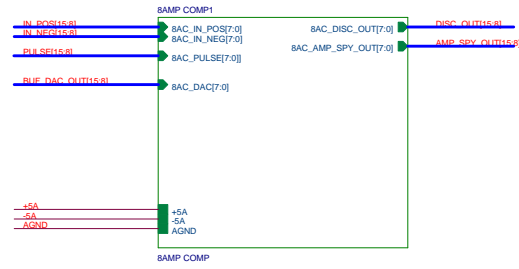
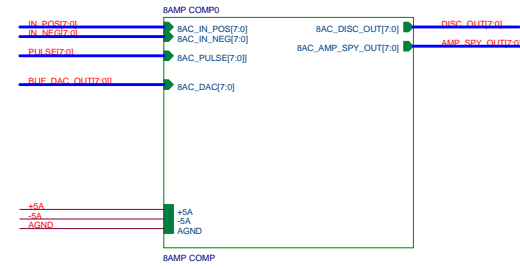
**CHANGES FROM REV0**

1. CHANGED DAC SERIAL BYPASS TO USE DGND
2. NO STUFF TEXT ADDED FOR CONNECTOR
3. ADDED DGND TO INPUT

# INPUTS



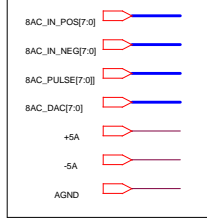
# OUTPUTS



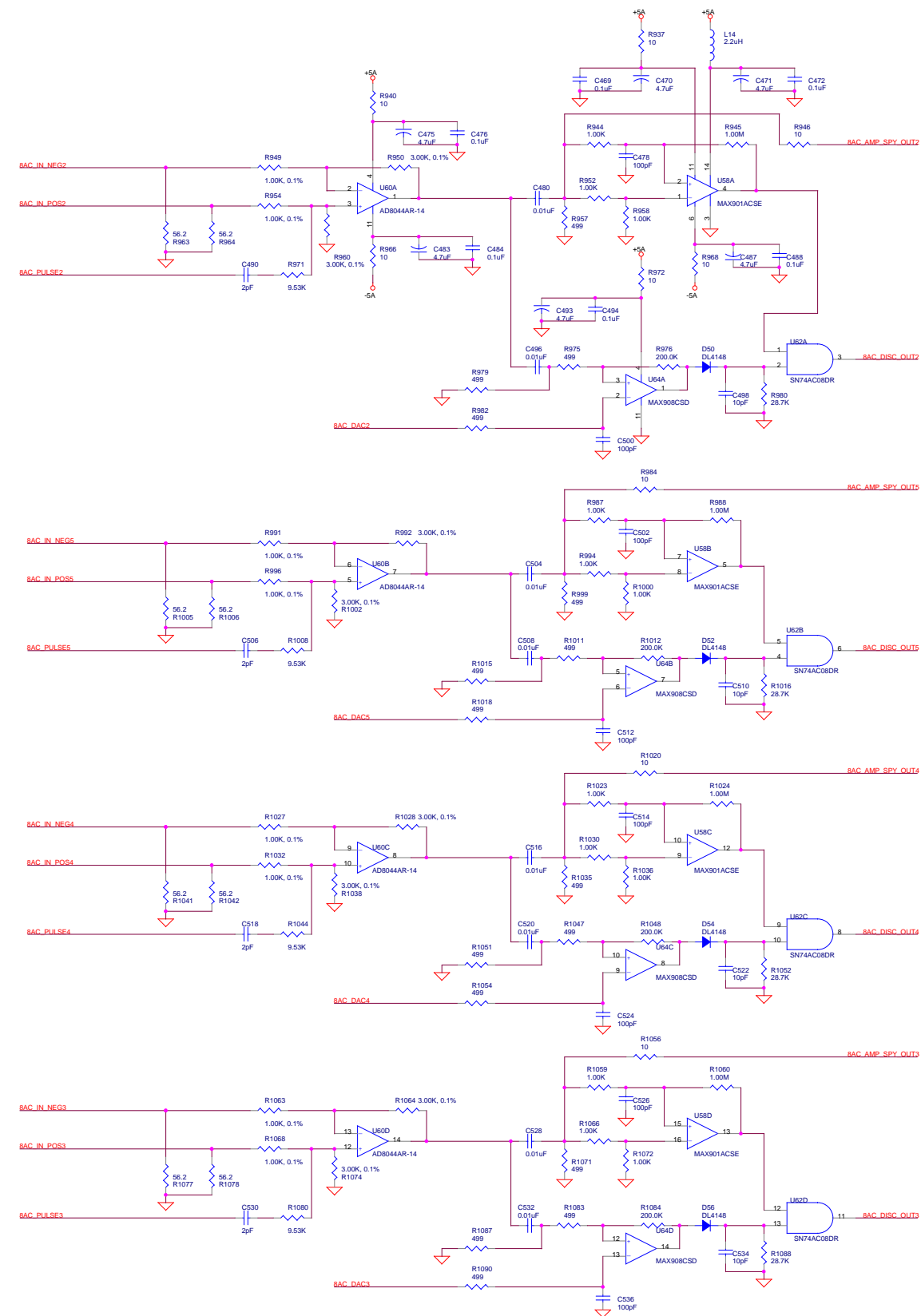
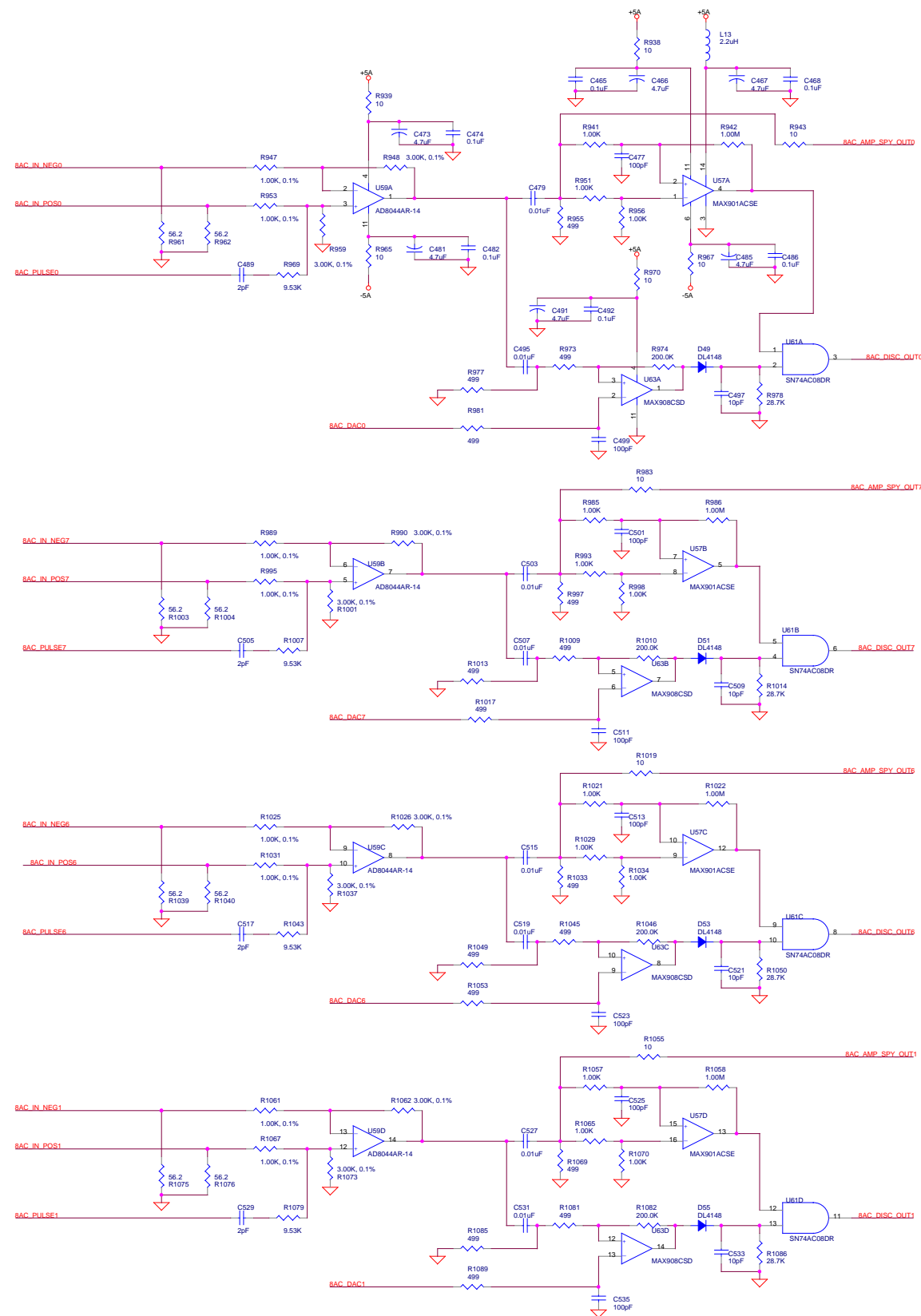
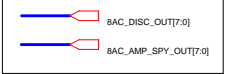
**CHANGES FROM REV0**  
NO CHANGES



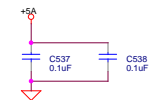
### INPUTS



### OUTPUTS



BYPASS CAPS BETWEEN PINS 7 AND 14 OF SN74AC08DR CHIPS

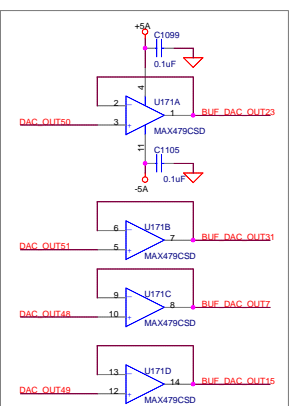
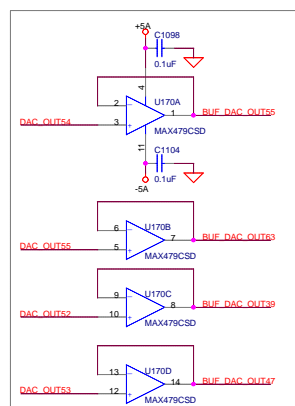
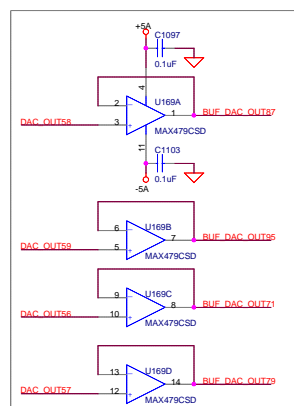
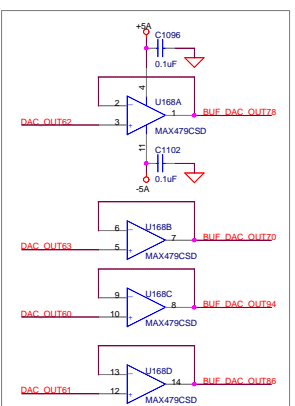
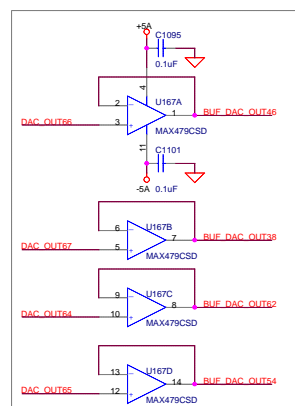
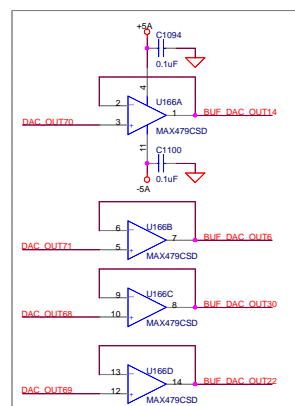
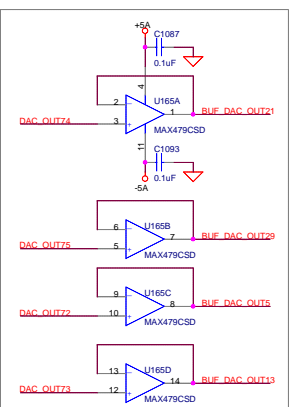
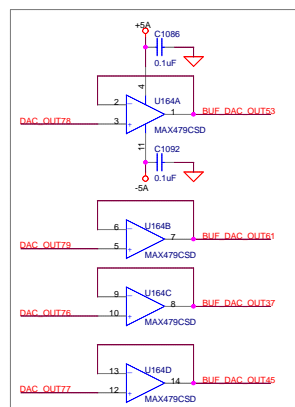
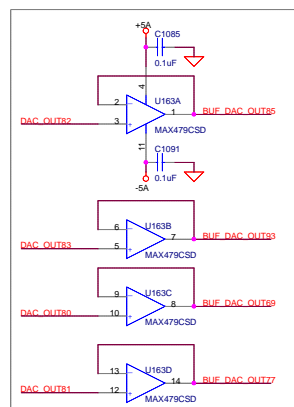
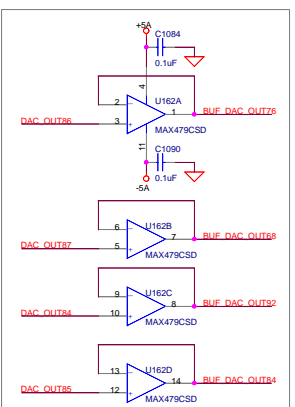
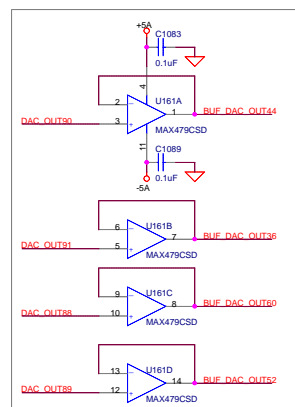
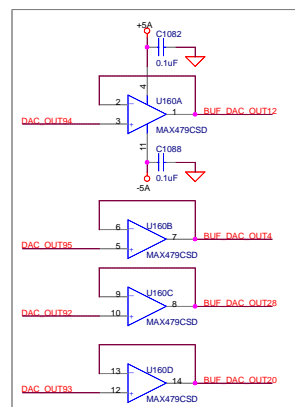
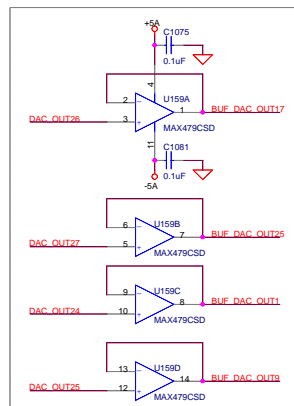
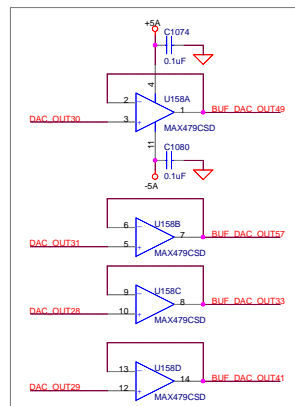
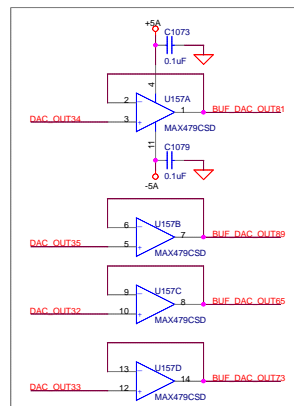
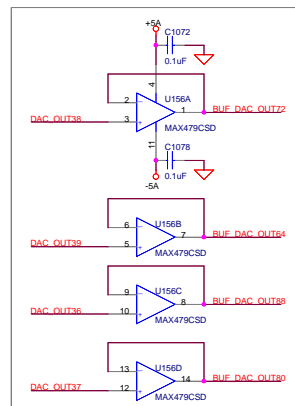
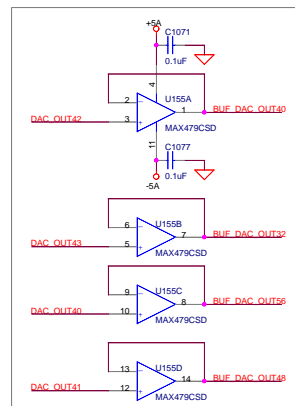
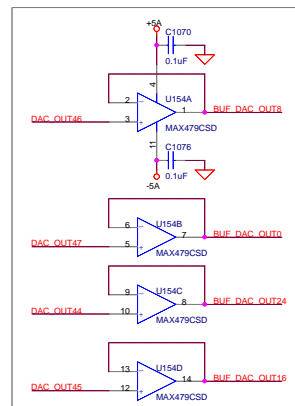
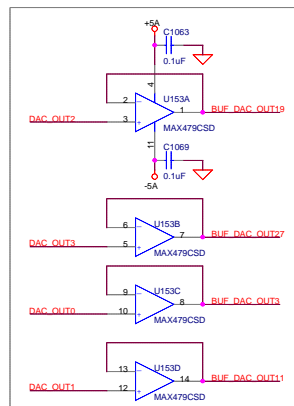
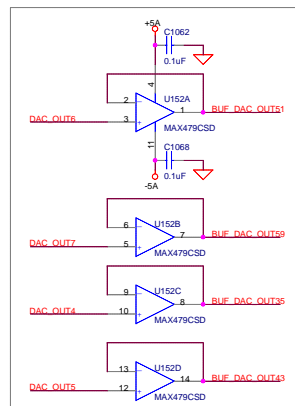
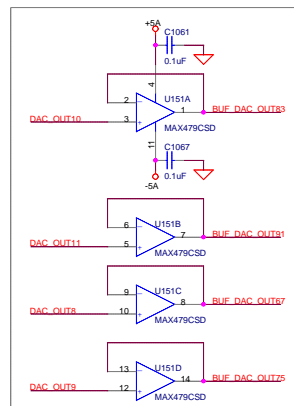
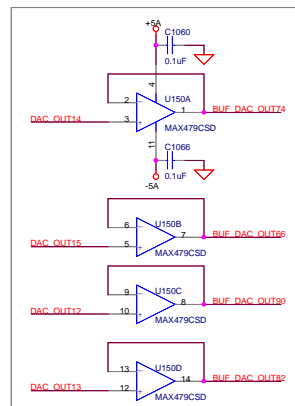
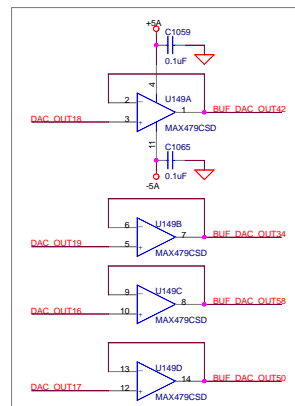
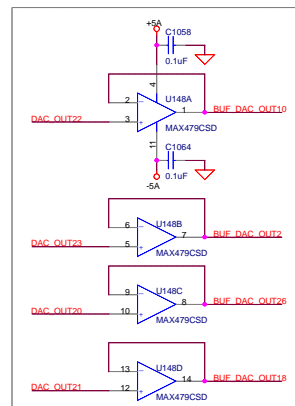


**CHANGES FROM REV0**  
 1. DAC FILTER CAPS CHANGED FROM 499pF TO 100pF  
 2. PULSER INPUT RESISTORS CHANGED FROM 49.9K TO 10K

### INPUTS



### OUTPUTS



**CHANGES FROM REV0**  
1. NO CHANGES